

Description

The μPD424263A/L and μPD42S4263A/L are fast-page dynamic RAMs with the write-per-bit option, organized as 262,144 words by 16 bits, and designed to operate from a single power supply.

Optional features are power supply voltage (+5 V or +3.3 V) and a new refresh mode called "self-refresh."

<u>μPD</u>	<u>Options</u>
424263A	+5 V
424263L	+3.3 V
42S4263A	+5 V; self-refresh mode
42S4263L	+3.3 V; self-refresh mode

Advanced polycide technology using stacked capacitors minimizes silicon area and provides high storage cell capacity, high performance, and high reliability. A single-transistor dynamic storage cell and CMOS circuitry throughout ensure minimum power dissipation, while an on-chip circuit internally generates the negative-voltage substrate bias—automatically and transparently.

The three-state I/O pins are controlled by UCAS and LCAS independent of RAS. After a valid read or read-modify-write cycle, upper or lower byte data is held on the outputs by maintaining UCAS or LCAS low. Data outputs return to high impedance when either UCAS or LCAS goes high. Fast-page read and write cycles can be executed by cycling UCAS or LCAS.

Refreshing may be accomplished by a CAS before RAS refresh cycle (CBR) that internally generates the refresh address. RAS-only refresh cycles will also refresh all memory locations.

The self-refresh mode is entered by holding RAS low for longer than 100 μs during a CBR cycle. Detection of this long RAS time starts an internal oscillator that maintains data integrity without external clocking. The slow refresh reduces the data hold current to less than 200 microamperes. Self-refresh mode is used with microprocessors that have a "sleep mode" for low-power applications such as notebook PCs.

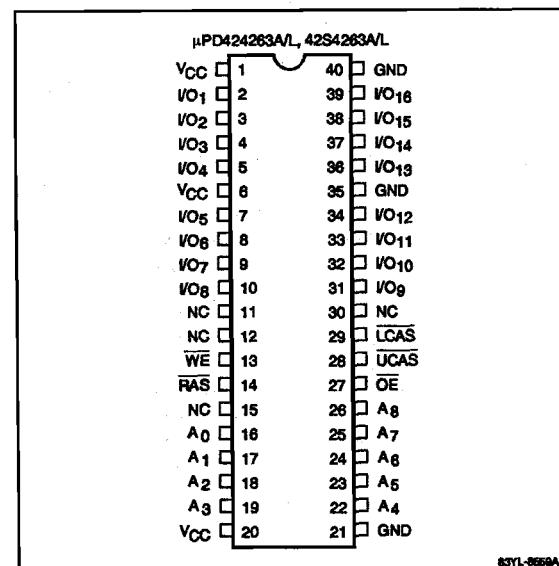
Features

- 262,144 by 16-bit organization
- Single power supply (+5-volt or +3.3-volt)
- Self-refresh option (slow internal automatic refresh)
- Fast-page option

- Byte read/write control with UCAS and LCAS
- Write-per-bit option; independent write control on 16 I/O's
- Low power dissipation
- CAS before RAS refreshing
- On-chip substrate bias generator
- TTL-compatible inputs and outputs
- Nonlatched, three-state outputs
- Low input capacitance
- Multiplexed row and column addresses
- 512 refresh cycles every 8 ms
- 40-pin SOJ, 40-pin ZIP, and 44/40-pin TSOP plastic packaging

Pin Configurations

40-Pin Plastic SOJ



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Pin Configurations (cont)

40-Pin Plastic ZIP

μPD424263A/L, 42S4263A/L	
VO ₉	1
VO ₁₁	3
GND	5
VO ₁₄	7
VO ₁₆	9
VCC	11
VO ₂	13
VO ₄	15
VO ₅	17
VO ₇	19
NC	21
WE	23
NC	25
A ₁	27
A ₃	29
GND	31
A ₅	33
A ₇	35
OE	37
LCAS	39
	40 NC

BSYL-6560A

44/40-Pin Plastic TSOP (Reverse Pinouts)

μPD424263A/L, 42S4263A/L	
GND	1 ○
VO ₁₆	2
VO ₁₅	3
VO ₁₄	4
VO ₁₃	5
GND	6
VO ₁₂	7
VO ₁₁	8
VO ₁₀	9
VO ₉	10
	○ 44 V _{CC}
NC	13
LCAS	14
UCAS	15
OE	16
A ₈	17
A ₇	18
A ₆	19
A ₅	20
A ₄	21
GND	22 ○

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BSYL-6560A

44/40-Pin Plastic TSOP (Normal Pinouts)

μPD424263A/L, 42S4263A/L	
V _{CC}	1 ○
VO ₁	2
VO ₂	3
VO ₃	4
VO ₄	5
VCC	6
VO ₅	7
VO ₆	8
VO ₇	9
VO ₈	10
	44 GND
NC	13
NC	14
WE	15
RAS	16
NC	17
A ₀	18
A ₁	19
A ₂	20
A ₃	21
V _{CC}	22 ○
	43 VO ₁₆
	42 VO ₁₅
	41 VO ₁₄
	40 VO ₁₃
	39 GND
	38 VO ₁₂
	37 VO ₁₁
	36 VO ₁₀
	35 VO ₉
	32 NC
	31 LCAS
	30 UCAS
	29 OE
	28 A ₈
	27 A ₇
	26 A ₆
	25 A ₅
	24 A ₄
	23 GND

-8JF

Suffix -8JF in the package identifier denotes normal pinout sequence.

BSYL-6561A

Pin Identification

A ₀ - A ₈	Address inputs
I/O ₁ - I/O ₁₆	Data inputs and outputs
LCAS, UCAS	Column address strobes
OE	Output enable
RAS	Row address strobe
WE	Write enable
GND	Ground
V _{CC}	+5-volt or +3.3-volt power supply
NC	No connection

Ordering Information, μ PD424263A (+ 5-volt power)

Part Number	RAS Access Time (max)	Fast-Page Cycle Time (max)	CAS Access Time (max)	Package
μ PD424263ALE-60	60 ns	40 ns	20 ns	40-pin plastic SOJ
LE-70	70 ns	45 ns		
LE-80	80 ns	50 ns		
μ PD424263AV-60	60 ns	40 ns	20 ns	40-pin plastic ZIP
V-70	70 ns	45 ns		
V-80	80 ns	50 ns		
μ PD424263AG5-60	60 ns	40 ns	20 ns	44/40-pin plastic TSOP (normal pinouts)
G5-70	70 ns	45 ns		
G5-80	80 ns	50 ns		
μ PD424263AG5M-60	60 ns	40 ns	20 ns	44/40-pin plastic TSOP (reverse pinouts)
G5M-70	70 ns	45 ns		
G5M-80	80 ns	50 ns		

Ordering Information, μ PD424263L (+ 3.3-volt power)

Part Number	RAS Access Time (max)	Fast-Page Cycle Time (max)	CAS Access Time (max)	Package
μ PD424263LLE-A60	60 ns	40 ns	20 ns	40-pin plastic SOJ
LE-A70	70 ns	45 ns		
LE-A80	80 ns	50 ns		
μ PD424263LV-A60	60 ns	40 ns	20 ns	40-pin plastic ZIP
V-A70	70 ns	45 ns		
V-A80	80 ns	50 ns		
μ PD424263LG5-A60	60 ns	40 ns	20 ns	44/40-pin plastic TSOP (normal pinouts)
G5-A70	70 ns	45 ns		
G5-A80	80 ns	50 ns		
μ PD424263LG5M-A60	60 ns	40 ns	20 ns	44/40-pin plastic TSOP (reverse pinouts)
G5M-A70	70 ns	45 ns		
G5M-A80	80 ns	50 ns		

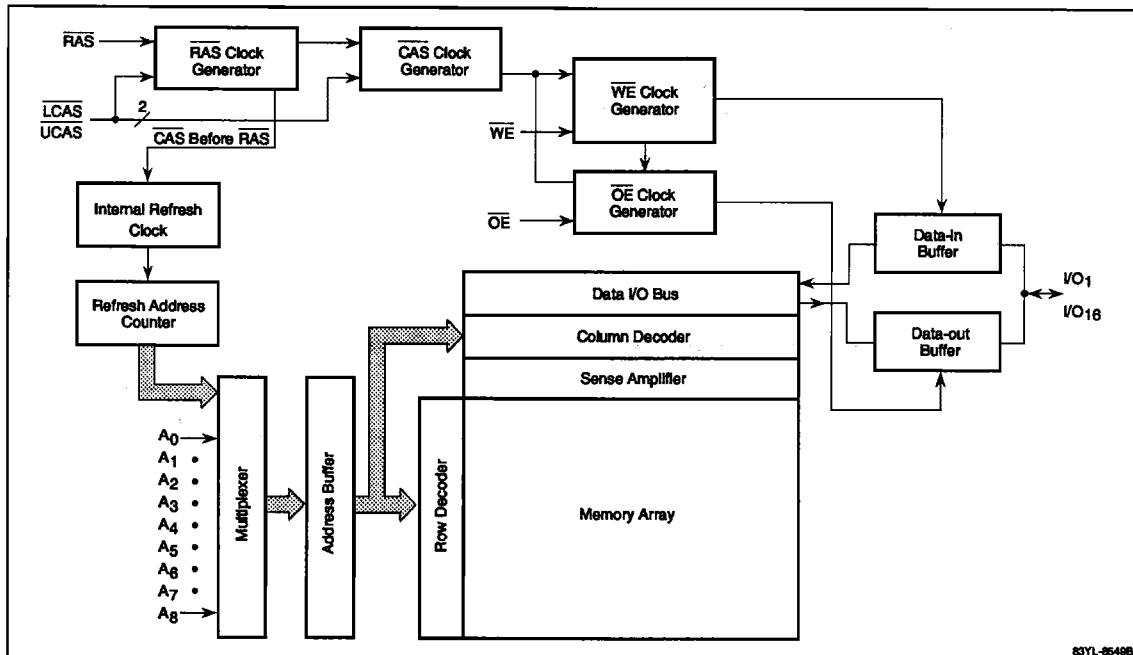
Ordering Information, μ PD42S4263A (+ 5-volt power; self-refresh mode)

Part Number	RAS Access Time (max)	Fast-Page Cycle Time (max)	CAS Access Time (max)	Self-Refresh Current (max)	Package
μ PD42S4263ALE-60	60 ns	40 ns	20 ns	300 μ A	40-pin plastic SOJ
LE-70	70 ns	45 ns			
LE-80	80 ns	50 ns			
μ PD42S4263AV-60	60 ns	40 ns	20 ns	300 μ A	40-pin plastic ZIP
V-70	70 ns	45 ns			
V-80	80 ns	50 ns			
μ PD42S4263AG5-60	60 ns	40 ns	20 ns	300 μ A	44/40-pin plastic TSOP (normal pinouts)
G5-70	70 ns	45 ns			
G5-80	80 ns	50 ns			
μ PD42S4263AG5M-60	60 ns	40 ns	20 ns	300 μ A	44/40-pin plastic TSOP (reverse pinouts)
G5M-70	70 ns	45 ns			
G5M-80	80 ns	50 ns			

Ordering Information, μ PD42S4263L (+ 3.3-volt power; self-refresh mode)

Part Number	RAS Access Time (max)	Fast-Page Cycle Time (max)	CAS Access Time (max)	Self-Refresh Current (max)	Package
μ PD42S4263LLE-A60	60 ns	40 ns	20 ns	100 μ A	40-pin plastic SOJ
LE-A70	70 ns	45 ns			
LE-A80	80 ns	50 ns			
μ PD42S4263LV-A60	60 ns	40 ns	20 ns	100 μ A	40-pin plastic ZIP
V-A70	70 ns	45 ns			
V-A80	80 ns	50 ns			
μ PD42S4263LG5-A60	60 ns	40 ns	20 ns	100 μ A	44/40-pin plastic TSOP (normal pinouts)
G5-A70	70 ns	45 ns			
G5-A80	80 ns	50 ns			
μ PD42S4263LG5M-A60	60 ns	40 ns	20 ns	100 μ A	44/40-pin plastic TSOP (reverse pinouts)
G5M-A70	70 ns	45 ns			
G5M-A80	80 ns	50 ns			

Block Diagram



83YL-8549B

Truth Table

Function	RAS	LCAS	UCAS	WE	OE	I/O ₁ - I/O ₈	I/O ₉ - I/O ₁₆
Standby	H	X	X	X	X	High-Z	High-Z
Refresh cycle	L	H	H	X	X	High-Z	High-Z
Byte read cycle	L	L	H	H	L	Data output	High-Z
	L	H	L	H	L	High-Z	Data output
Word read cycle	L	L	L	H	L	Data output	Data output
Byte write cycle	L	L	H	L	H	Data input	—
	L	H	L	L	H	—	Data input
Word write cycle	L	L	L	L	H	Data input	Data input
—	L	L	L	H	H	High-Z	High-Z

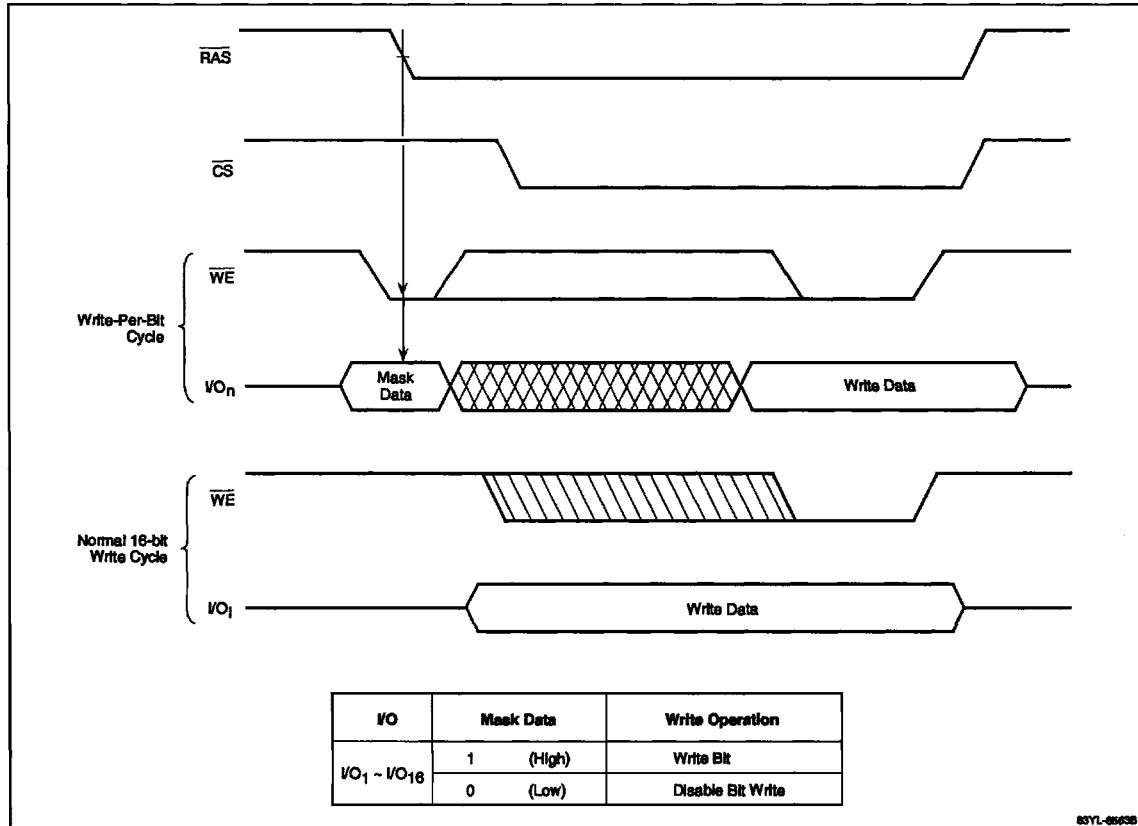
X = don't care.

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Write-Per-Bit Option

The write-per-bit option may be used to allow a write cycle to change any number of bits in the 16-bit word. The mask is loaded from the I/O lines at the falling edge of RAS if WE = V_{IL}. If the I/O line is high, then the corresponding bit will be written when the write cycle executes. If the I/O line is low, the bit does not change. A mask loaded during fast-page operation will remain set and active for each write cycle that executes while RAS remains low. The mask may be changed only at the falling edge of RAS.

Comparison of Write-Per-Bit Cycle Versus Standard 16-Bit Write Cycle



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Absolute Maximum Ratings

Voltage on any pin relative to GND	
5-volt devices	-1.0 to +7.0 V
3.3-volt devices	-0.5 to +4.6 V
Operating temperature, T_{OPR}	0 to +70°C
Storage temperature, T_{STG}	-55 to +125°C
Short-circuit output current, I_{OS}	
5-volt devices	50 mA
3.3-volt devices	20 mA
Power dissipation, P_D	1.0 W

Exposure to Absolute Maximum Ratings for extended periods may affect device reliability; exceeding the ratings could cause permanent damage. The device should be operated within the limits specified under DC and AC Characteristics.

Capacitance

$T_A = 25^\circ\text{C}$; $f = 1 \text{ MHz}$

Parameter	Symbol	Max	Unit	Pins Under Test
Input capacitance	C_{I1}	5	pF	Addresses
	C_{I2}	7	pF	$\overline{\text{LCAS}}, \overline{\text{UCAS}}, \overline{\text{WE}}, \overline{\text{OE}}, \overline{\text{RAS}}$
Input/output capacitance	C_O	7	pF	$\overline{\text{I/O}}_1 - \overline{\text{I/O}}_{16}$

Recommended Operating Conditions

Parameter	Symbol	5-Volt Devices			3.3-Volt Devices			Unit
		Min	Typ	Max	Min	Typ	Max	
Input voltage, high	V_{IH}	2.4		$V_{CC} + 1.0$	2.0		$V_{CC} + 0.3$	V
Input voltage, low	V_{IL}	-1.0		0.8	-0.5		0.8	V
Supply voltage	V_{CC}	4.5	5.0	5.5	3.0	3.3	3.6	V
Ambient temperature	T_A	0		+70	0		+70	°C

Self-Refresh Current

$T_A = 0$ to $+70^\circ\text{C}$; $V_{CC} = +5 \text{ V} \pm 10\%$ (42S4263A) or $+3.3 \text{ V} \pm 0.3 \text{ V}$ (42S4263L)

Symbol	42S4263A	42S4263L	Conditions
I_{CC7}	300 μA max	100 μA max	I/O pins: $V_{IH} \geq V_{CC} - 0.2 \text{ V}$; $V_{IL} \leq 0.2 \text{ V}$ or open. Other input pins: $V_{IH} \geq V_{CC} - 0.2 \text{ V}$; $V_{IL} \leq 0.2 \text{ V}$ or open. $t_{RAS} \geq 100 \mu\text{s}$

DC Characteristics; 5-Volt Devices $T_A = 0 \text{ to } +70^\circ\text{C}; V_{CC} = +5.0 \text{ V } \pm 10\%$

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions
Standby current	I_{CC2}			2.0	mA	$\overline{RAS} = \overline{CAS} \geq V_{IH}$ (min); $I_O = 0 \text{ mA}$
				300	μA	$\overline{RAS} = \overline{CAS} \geq V_{CC} - 0.2 \text{ V}; I_O = 0 \text{ mA}$
Input leakage current	$I_{IL(L)}$	-10		10	μA	$V_{IN} = 0 \text{ V to } V_{CC}$; all other pins not under test = 0 V
Output leakage current	$I_{OL(L)}$	-10		10	μA	D_{OUT} disabled; $V_{OUT} = 0 \text{ V to } V_{CC}$
Output voltage, low	V_{OL}			0.4	V	$I_{OL} = 4.2 \text{ mA}$
Output voltage, high	V_{OH}	2.4			V	$I_{OH} = -5 \text{ mA}$

DC Characteristics; 3.3-Volt Devices $T_A = 0 \text{ to } +70^\circ\text{C}; V_{CC} = +3.3 \text{ V } \pm 0.3 \text{ V}$

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions
Standby current	I_{CC2}			500	μA	$\overline{RAS} = \overline{CAS} \geq V_{IH}$ (min); $I_O = 0 \text{ mA}$
				100	μA	$\overline{RAS} = \overline{CAS} \geq V_{CC} - 0.2 \text{ V}; I_O = 0 \text{ mA}$
Input leakage current	$I_{IL(L)}$	-5		5	μA	$V_{IN} = 0 \text{ V to } V_{CC}$; all other pins not under test = 0 V
Output leakage current	$I_{OL(L)}$	-5		5	μA	D_{OUT} disabled; $V_{OUT} = 0 \text{ V to } V_{CC}$
Output voltage, low	V_{OL}			0.4	V	$I_{OL} = 2.0 \text{ mA}$
Output voltage, high	V_{OH}	2.4			V	$I_{OH} = -2.0 \text{ mA}$

AC Characteristics $T_A = 0 \text{ to } +70^\circ\text{C}$ μ PD424263A, 42S4263A: $V_{CC} = +5.0 \text{ V } \pm 10\%$ μ PD424263L, 42S4263L: $V_{CC} = +3.3 \text{ V } \pm 0.3 \text{ V}$

Parameter	Symbol	-60		-70		-80		Unit	Test Conditions
		Min	Max	Min	Max	Min	Max		
Operating current, average	$I_{CC1(+5)}$	140		130		120		mA	$\overline{RAS}, \overline{CAS}$ cycling; $t_{RC} = t_{RC}$ min (Note 5)
	$I_{CC1(+3.3)}$	130		120		110			
Operating current, RAS-only refresh cycle, average	$I_{CC3(+5)}$	140		130		120		mA	\overline{RAS} cycling; $\overline{CAS} \geq V_{IH}$ min; $t_{RC} = t_{RC}$ min (Note 5)
	$I_{CC3(+3.3)}$	130		120		110			
Operating current, fast-page cycle, average	$I_{CC4(+5)}$	90		80		70		mA	$\overline{RAS} \leq V_{IL}; \overline{CAS}$ cycling; $t_{PC} = t_{PC}$ min (Note 5)
	$I_{CC4(+3.3)}$	90		80		70			
Operating current, CAS before RAS refresh cycle, average	$I_{CC5(+5)}$	140		130		120		mA	\overline{RAS} cycling; $\overline{CAS} \leq V_{IL}$ max; $t_{RC} = t_{RC}$ min (Note 5)
	$I_{CC5(+3.3)}$	130		120		110			
Access time from column address	t_{AA}	30		35		40		ns	(Notes 3, 4, 7, 8)
Access time from CAS precharge (rising edge)	t_{ACP}	35		40		45		ns	(Notes 3, 4, 7, 8, 16)
Column address setup time	t_{ASC}	0		0		0		ns	
Row address setup time	t_{ASR}	0		0		0		ns	
Column address to WE delay time	t_{AWD}	50		55		70		ns	(Note 14)

AC Characteristics (cont)

Parameter	Symbol	-60		-70		-80		Unit	Test Conditions
		Min	Max	Min	Max	Min	Max		
Access time from CAS (falling edge)	t_{CAC}		20		20		20	ns	(Notes 3, 4, 7, 8)
Column address hold time	t_{CAH}	15		15		15		ns	
CAS pulse width	t_{CAS}	20	10,000	20	10,000	20	10,000	ns	
CAS hold time for CAS before RAS refreshing	t_{CHR}	15		15		15		ns	(Note 15)
CAS hold time (CBR self-refresh mode)	t_{CHS}	-35		-40		-50		ns	For 42S4263A/L only
CAS to output in low-Z	t_{CLZ}	0		0		0		ns	(Notes 4, 7)
Fast-page CAS precharge time	t_{CP}	10		10		10		ns	
CAS precharge time	t_{CPN}	10		10		10		ns	
Fast-page CAS precharge to WE delay time	t_{CPWD}	55		60		75		ns	(Note 14)
CAS to RAS precharge time	t_{CRP}	10		10		10		ns	(Note 10)
CAS hold time	t_{CSH}	60		70		80		ns	
CAS setup time for CAS before RAS refresh cycle	t_{CSR}	5		5		5		ns	(Note 15)
CAS to WE delay	t_{CWD}	40		40		50		ns	(Note 14)
Write command referenced to CAS lead time	t_{CWL}	15		15		15		ns	
Data-in hold time	t_{DH}	15		15		15		ns	(Note 13)
Data-in setup time	t_{DS}	0		0		0		ns	(Note 13)
Masked write hold time referenced to RAS	t_{MRH}	0		0		0		ns	
Access time from OE	$t_{OE A}$		20		20		20	ns	(Notes 3, 4, 7, 8)
OE data delay time	t_{OED}	15		15		15		ns	
OE command hold time	t_{OEH}	0		0		0		ns	
OE to RAS inactive setup time	t_{OES}	0		0		0		ns	
Output turnoff delay from OE	t_{OEZ}	0	15	0	15	0	15	ns	(Note 9)

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AC Characteristics (cont)

Parameter	Symbol	-60		-70		-80		Unit	Test Conditions
		Min	Max	Min	Max	Min	Max		
Output disable from CAS high	t_{OFF}	0	15	0	15	0	20	ns	(Note 9)
\overline{OE} to output in low-Z	t_{OLZ}	0		0		0		ns	(Notes 5, 7)
Fast-page read or write cycle time	t_{PC}	40		45		50		ns	(Note 6)
Fast-page read-modify-write cycle time with extended data output	t_{PRWC}	85		90		100		ns	(Note 6)
Access time from RAS	t_{RAC}		60		70		80	ns	(Notes 3, 4, 7, 8)
RAS to column address delay time	t_{RAD}	15	30	15	35	15	40	ns	(Note 8)
Row address hold time	t_{RAH}	10		10		10		ns	
Column address lead time referenced to RAS (rising edge)	t_{RAL}	30		35		40		ns	
RAS pulse width	t_{RAS}	60	10,000	70	10,000	80	10,000	ns	
Fast-page RAS pulse width	t_{RASP}	60	125,000	70	125,000	80	125,000	ns	
RAS pulse width (CBR self-refresh mode)	t_{RASS}	100		100		100		μ s	For 42S4263A/L
Random read or write cycle time	t_{RC}	120		130		150		ns	(Note 6)
RAS to CAS delay time	t_{RCD}	20	40	20	50	20	60	ns	(Note 8)
Read command hold time referenced to CAS	t_{RCH}	0		0		0		ns	(Note 11)
Read command setup time	t_{RCS}	0		0		0		ns	
Refresh period	t_{REF}		8		8		8	ms	Addresses A ₀ - A ₈
RAS hold time referenced to CAS precharge	t_{RHCP}	35		40		45		ns	
RAS precharge time	t_{RP}	50		50		60		ns	
RAS precharge CAS hold time	t_{RPC}	0		0		0		ns	
RAS precharge time (CBR self-refresh mode)	t_{RPS}	120		130		150		ns	For 42S4263A/L
Read command hold time referenced to RAS	t_{RRH}	0		0		0		ns	(Note 11)

AC Characteristics (cont)

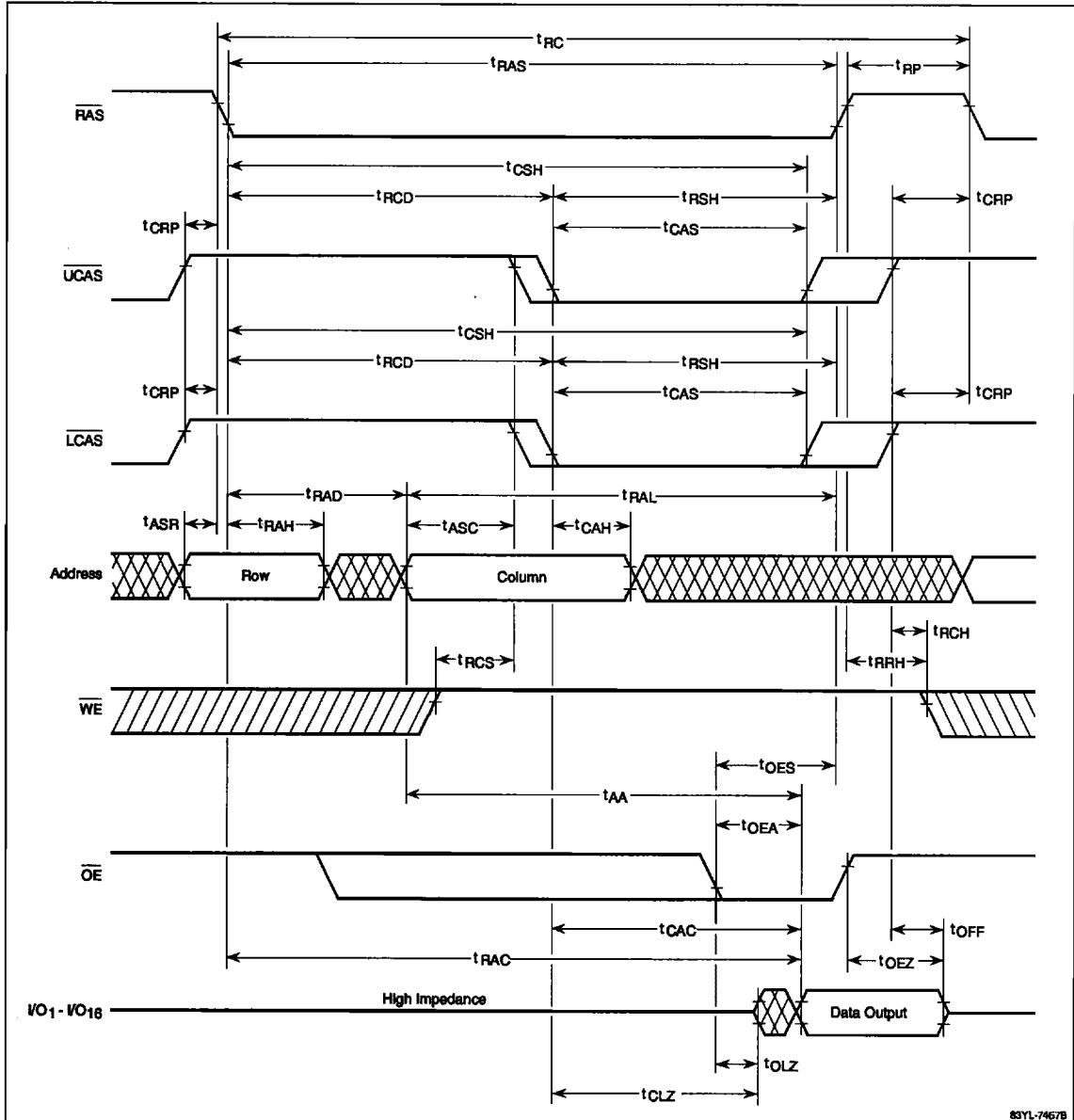
Parameter	Symbol	-60		-70		-80		Unit	Test Conditions
		Min	Max	Min	Max	Min	Max		
RAS hold time	t_{RSH}	20		20		25		ns	
Read-modify-write cycle time	t_{RWC}	165		175		200		ns	(Note 6)
RAS to WE delay	t_{RWD}	80		90		105		ns	(Note 14)
Write command referenced to RAS lead time	t_{RWL}	20		20		20		ns	
Rise and fall times	t_T	3	50	3	50	3	50	ns	(Note 4)
Write-per-bit hold time	t_{WBH}	10		10		15		ns	
Write-per-bit setup time	t_{WBS}	0		0		0		ns	
Write command hold time	t_{WCH}	15		15		15		ns	(Note 12)
Write command setup time	t_{WCS}	0		0		0		ns	(Note 14)
Write mask data hold time	t_{WH}	10		10		15		ns	
Write command pulse width	t_{WP}	15		15		15		ns	(Note 12)
Write mask data setup time	t_{WS}	0		0		0		ns	

Notes:

- (1) All voltages are referenced to GND.
- (2) An initial pause of 100 μ s is required after power-up, followed by any eight RAS cycles, before proper device operation is achieved.
- (3) Ac measurements assume $t_T = 5$ ns.
- (4) V_{IH} (min) and V_{IL} (max) are reference levels for measuring the timing of input signals. Transition times are measured between V_{IH} and V_{IL} .
- (5) I_{CC1} , I_{CC3} , I_{CC4} , and I_{CC5} depend on output loading and cycle rates. Specified values are obtained with the output open. I_{CC3} is measured assuming that all column address inputs are held at either a high level or a low level during RAS-only refresh cycles. I_{CC4} is measured assuming that all column address inputs are switched only once during each fast-page cycle.
- (6) The minimum specifications are used only to indicate the cycle time at which proper operation over the full temperature range ($T_A = 0$ to +70°C) is assured.
- (7) Load = 2 TTL (-1 mA, +4 mA) loads and 100 pF. For 3.3-volt devices, $V_{OH} = 2.0$ volts and $V_{OL} = 0.8$ volt (ac reference levels)
- (8) If $t_{RCR} \leq t_{RCD}$ (max) and $t_{RAD} \leq t_{RAD}$ (max), access time is defined by t_{RAC} (max). If $t_{RCR} \geq t_{RCD}$ (max), access time is defined by t_{CAC} (max); if $t_{RAD} \geq t_{RAD}$ (max) access time is defined by t_{AA} (max).
- (9) t_{OFF} (max) and t_{OEZ} (max) define the time at which the outputs become open-circuit and are not referenced to V_{OH} or V_{OL} .
- (10) The t_{CRP} requirement should be applicable for RAS/CAS cycles preceded by any cycle.
- (11) Either t_{RRH} or t_{RCH} must be satisfied for a read cycle.
- (12) Parameter t_{WP} is applicable for a delayed write cycle such as a read-write/read-modify-write cycle. For early write cycles, both t_{WCS} and t_{WCH} must be met.
- (13) These parameters are referenced to the falling edge of one of the CAS signals for early write cycles and to the falling edge of WE for delayed write or read-modify-write cycles.
- (14) t_{WCS} , t_{RWD} , t_{CWD} , t_{CPWD} and t_{AWD} are restrictive operating parameters in read-write/read-modify-write cycles only. If $t_{WCS} \geq t_{WCS}$ (min), the cycle is an early write cycle and the data I/O pins will remain open-circuit throughout the entire cycle. If $t_{CWD} \geq t_{CWD}$ (min), $t_{RWD} \geq t_{RWD}$ (min), and $t_{AWD} \geq t_{AWD}$ (min), then the cycle is a read-write cycle and the data I/O pins will contain data read from the selected cells. If neither of the above conditions is met, the condition of the data I/O pins (at access time and until CAS returns to V_{IH}) is indeterminate.
- (15) Holding LCAS or UCAS low prior to RAS going negative will initiate a CAS before RAS refresh cycle (t_{CSR} and t_{CHR} must be satisfied).
- (16) The first CAS falling edge is used as a reference for the start of t_{ACP} (CAS precharge access time).

Timing Waveforms

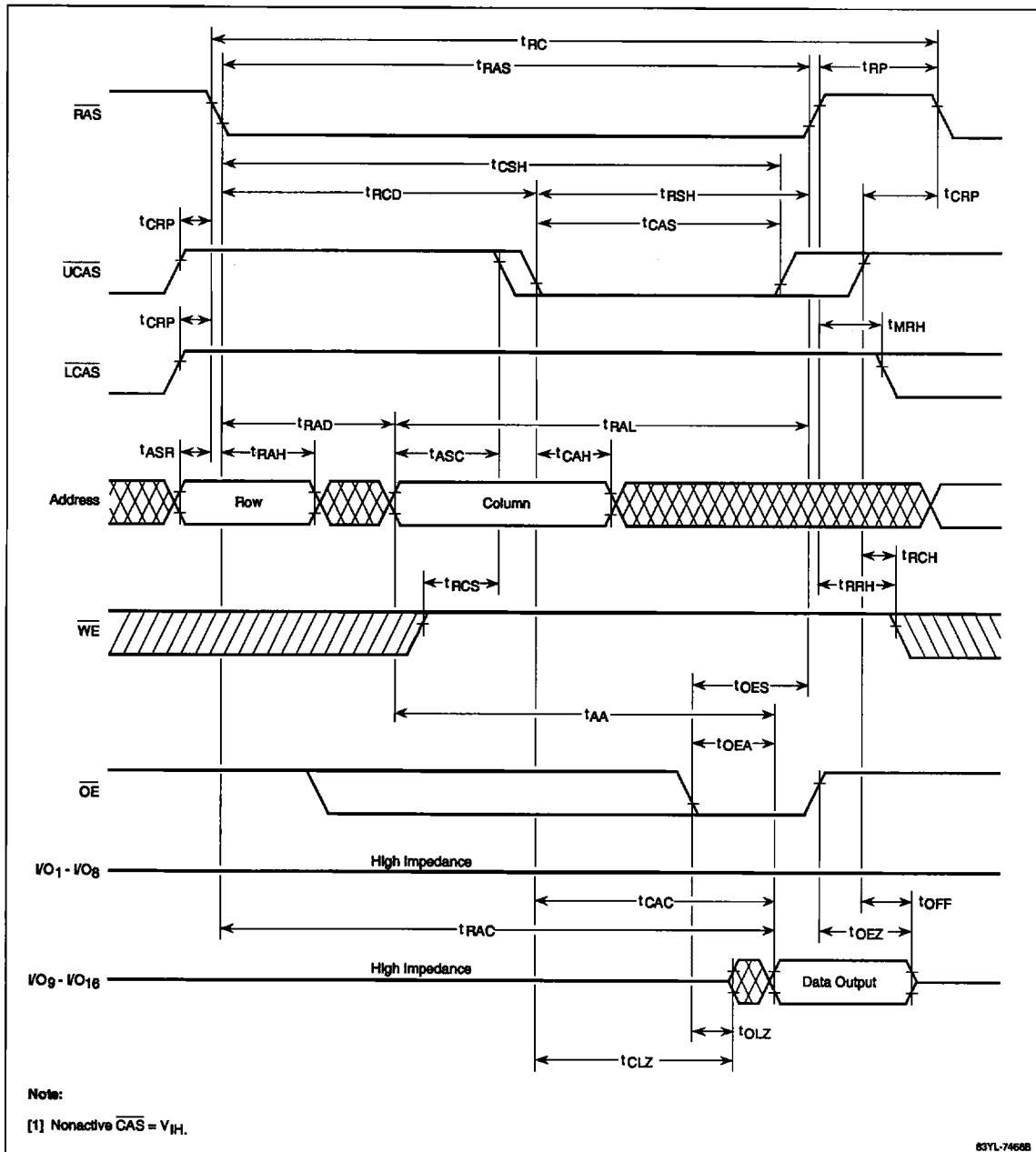
Word Read Cycle



83YL-7467B

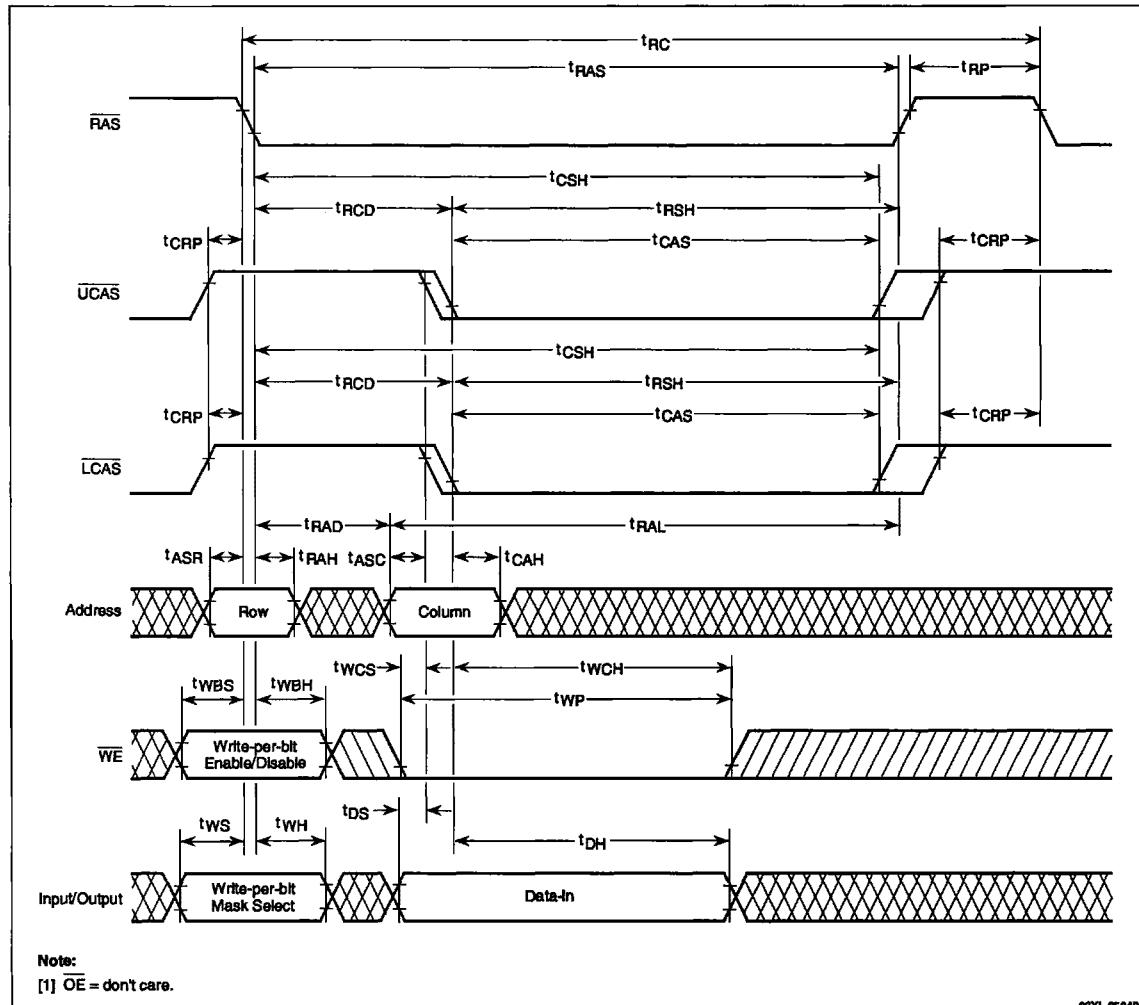
Timing Waveforms (cont)

Byte Read Cycle



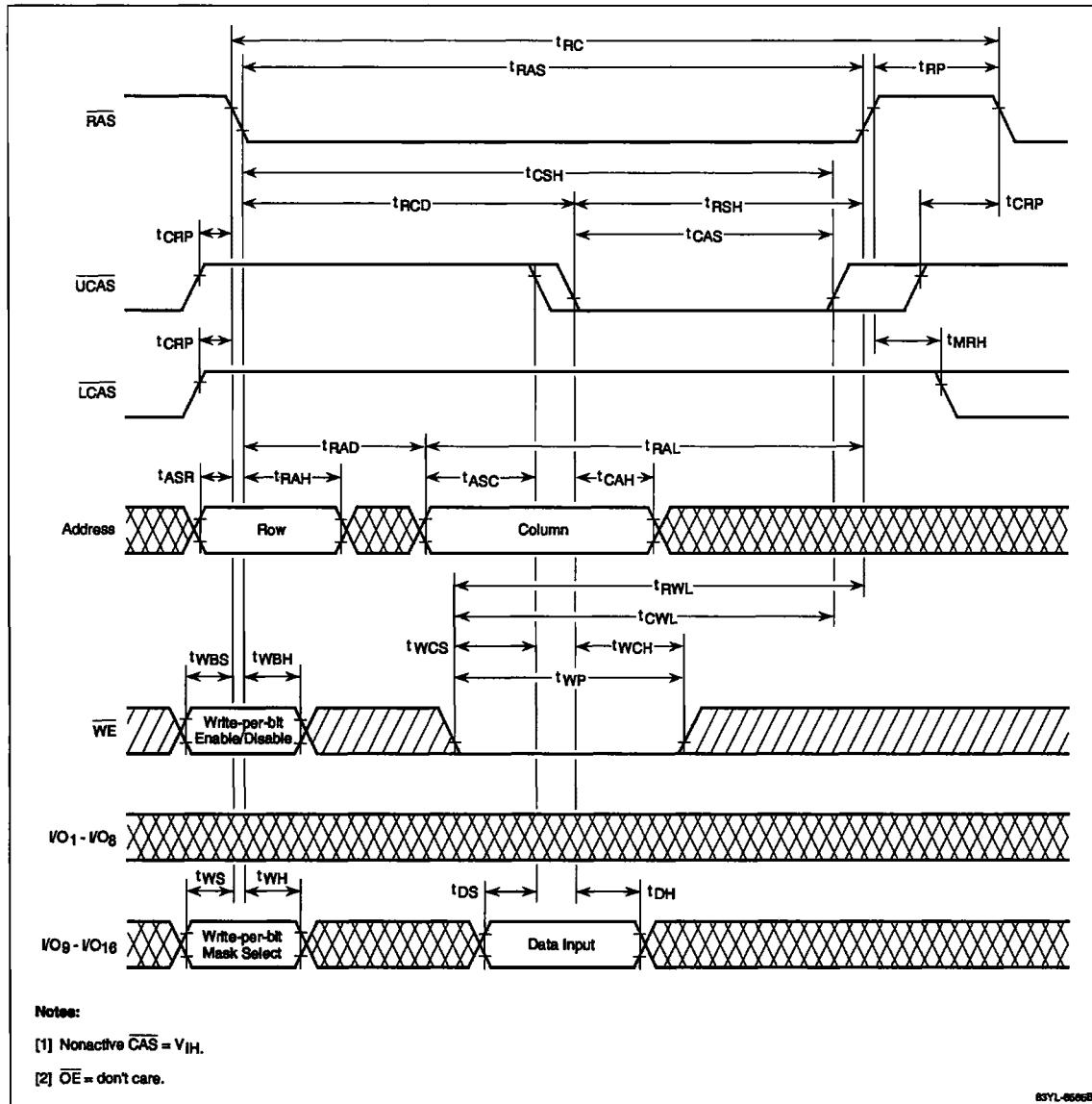
Timing Waveforms (cont)

Word Early-Write Cycle



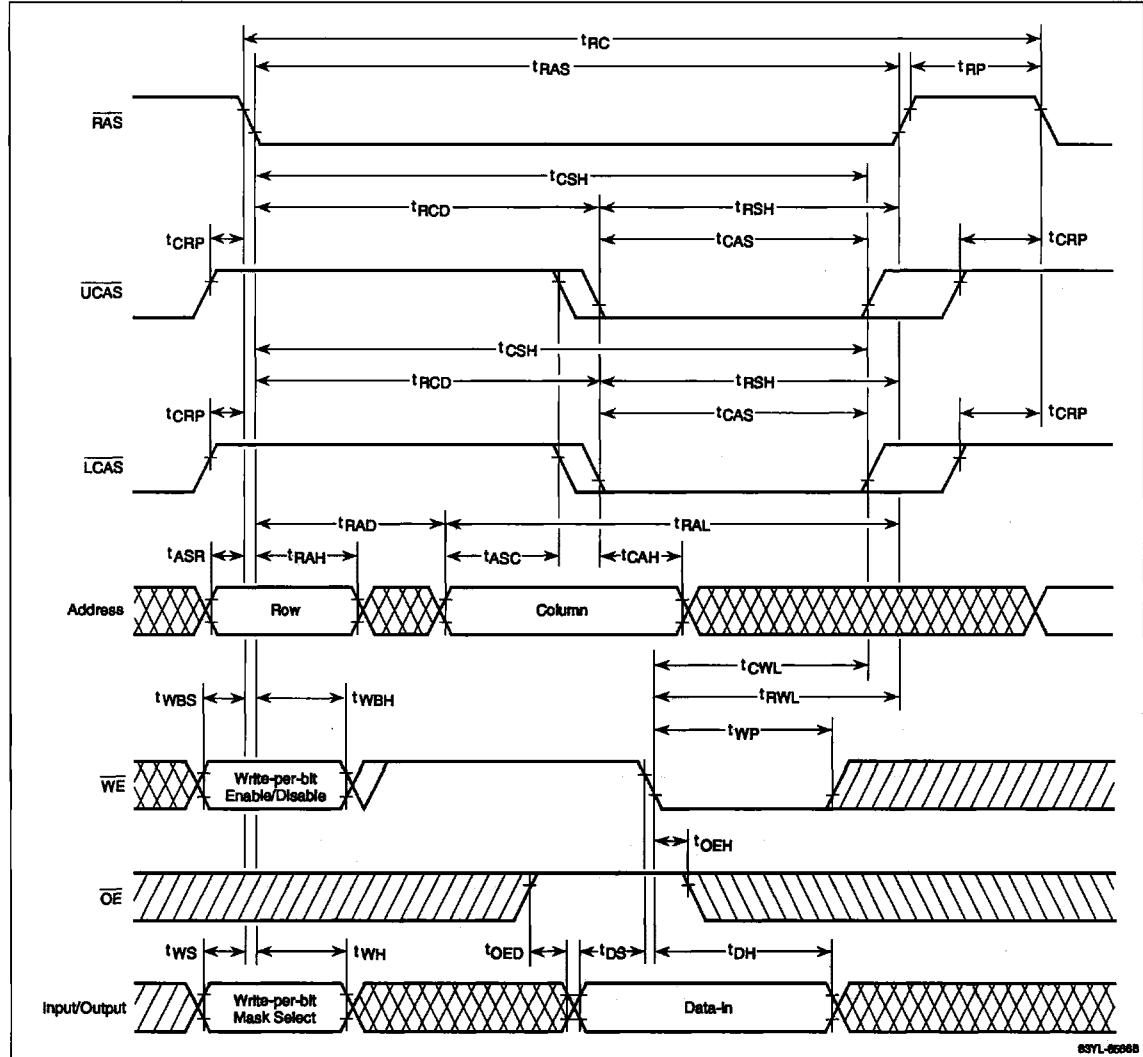
Timing Waveforms (cont)

Byte Early-Write Cycle



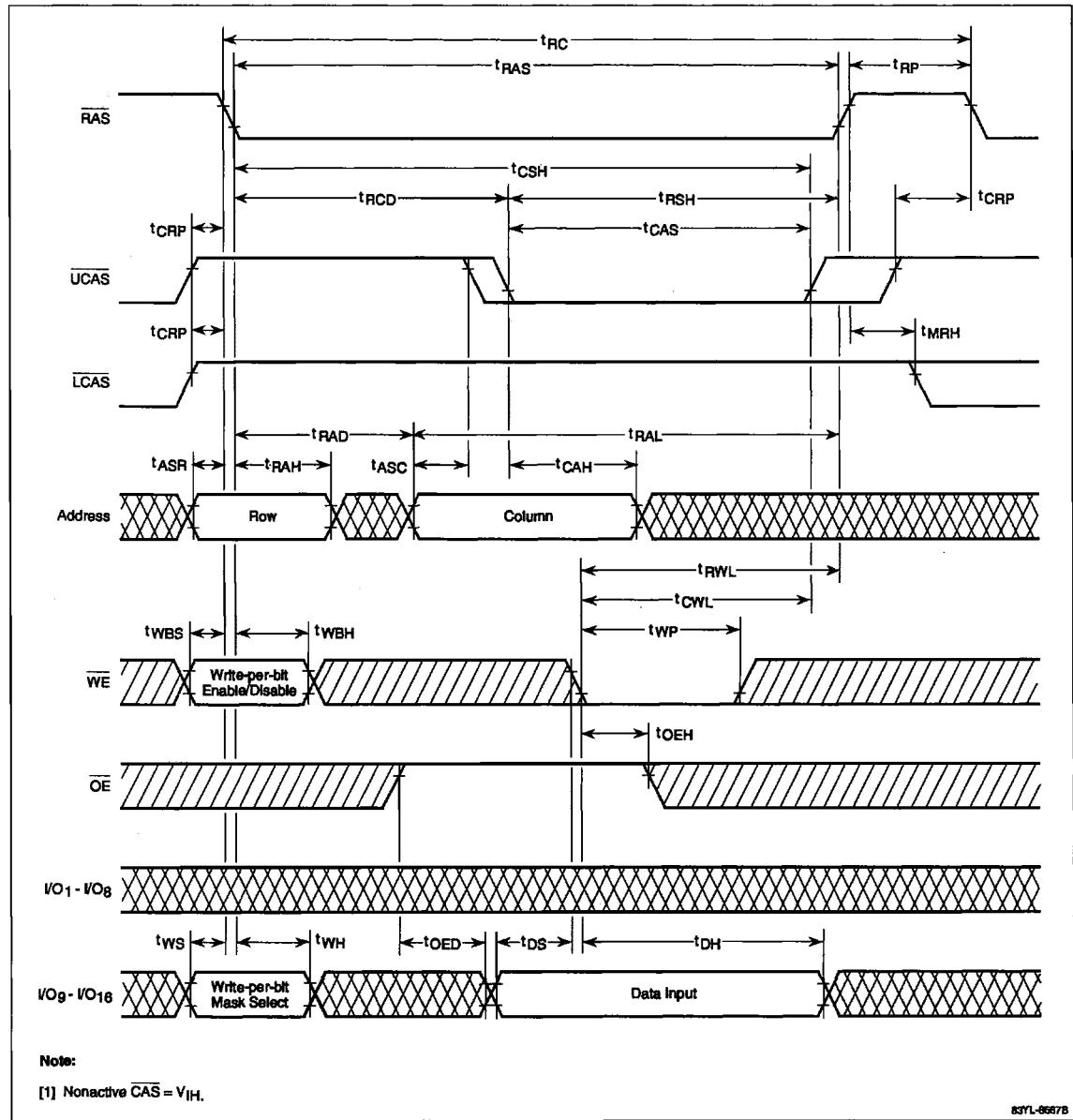
Timing Waveforms (cont)

Word Late-Write Cycle



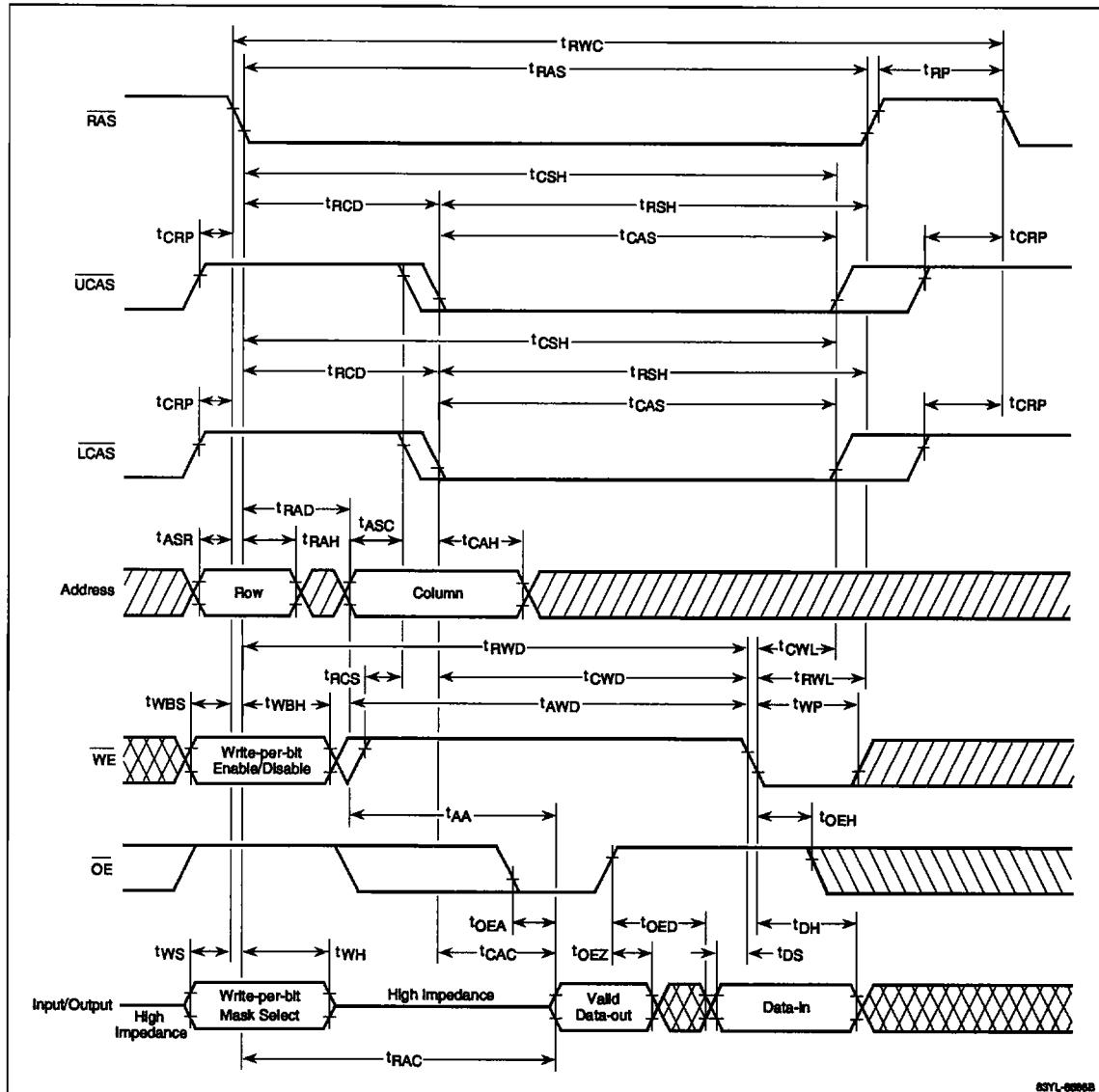
Timing Waveforms (cont)

Byte Late-Write Cycle



Timing Waveforms (cont)

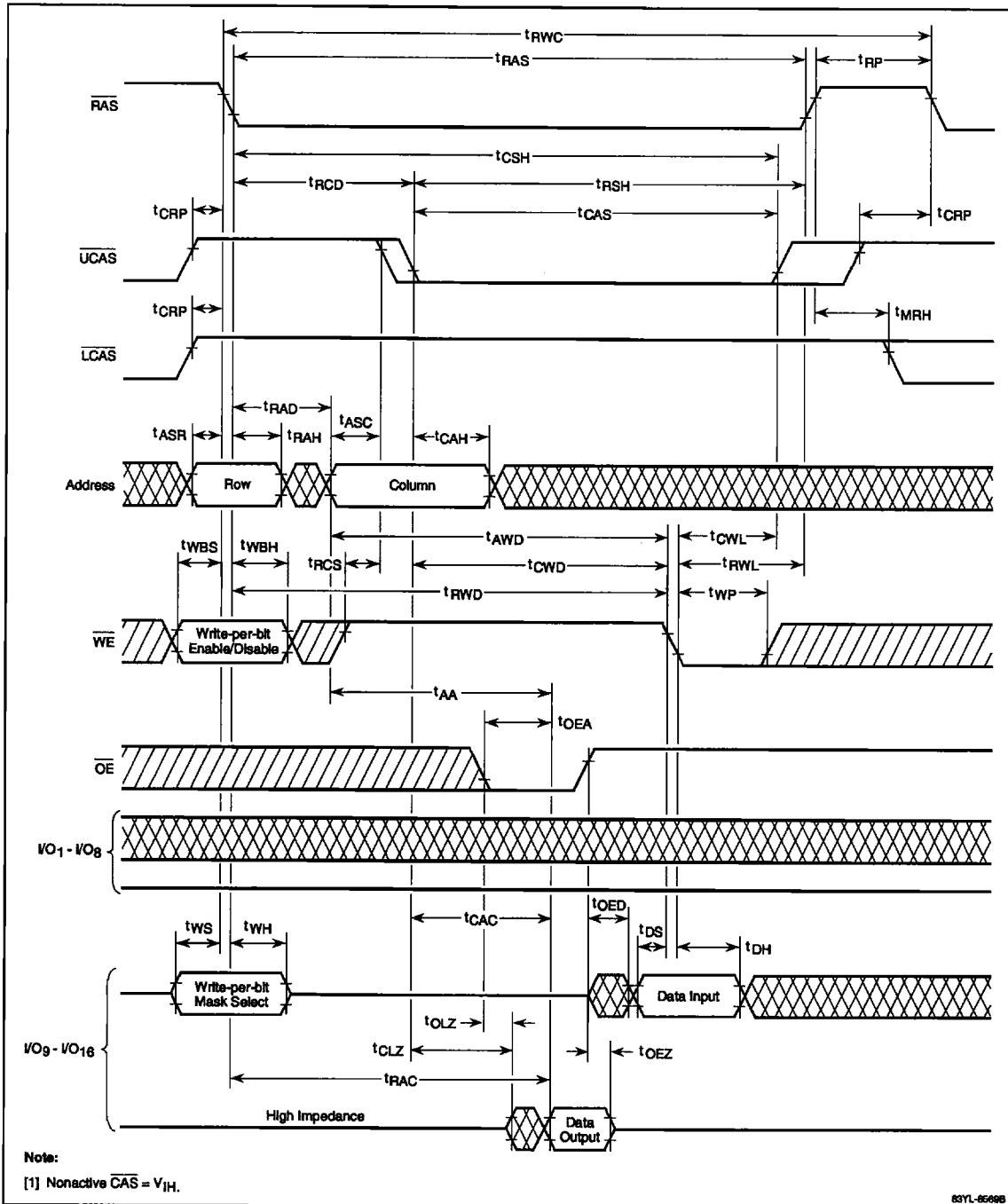
Word Read-Modify-Write Cycle



6SYL-6996B

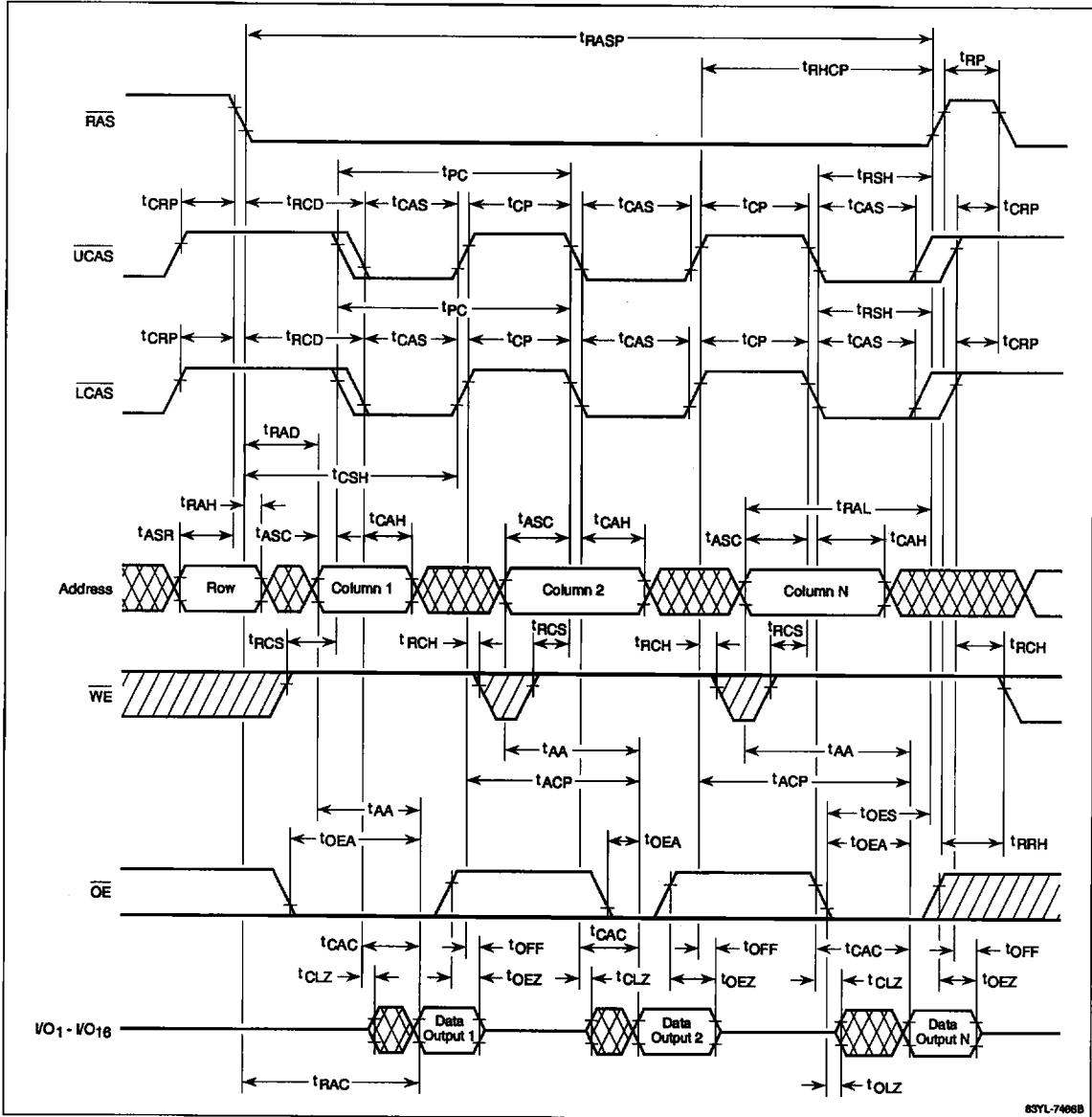
Timing Waveforms (cont)

Byte Read-Modify-Write Cycle



Timing Waveforms (cont)

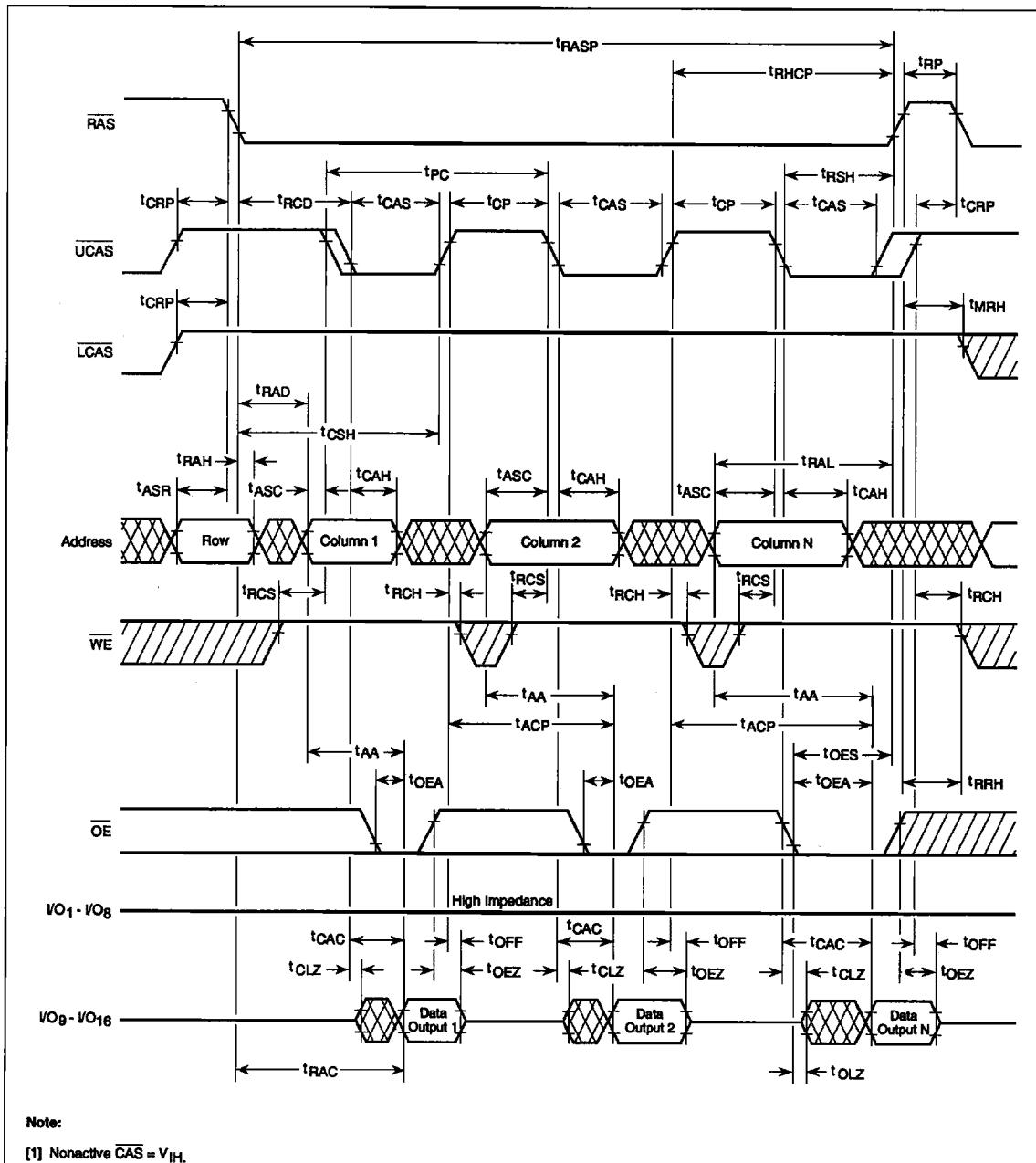
Word Fast-Page Read Cycle



8SYL-7466B

Timing Waveforms (cont)

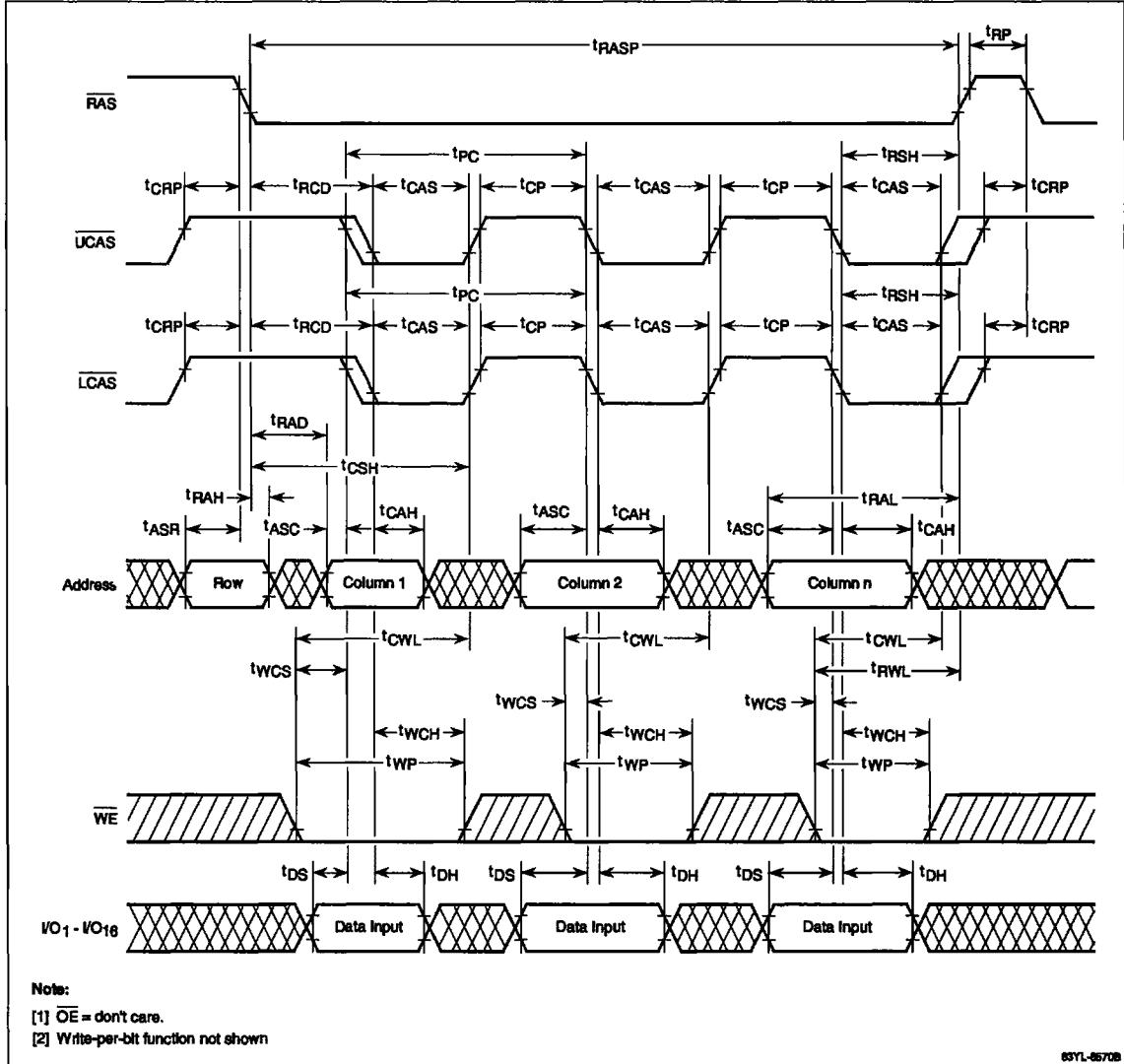
Byte Fast-Page Read Cycle



7d

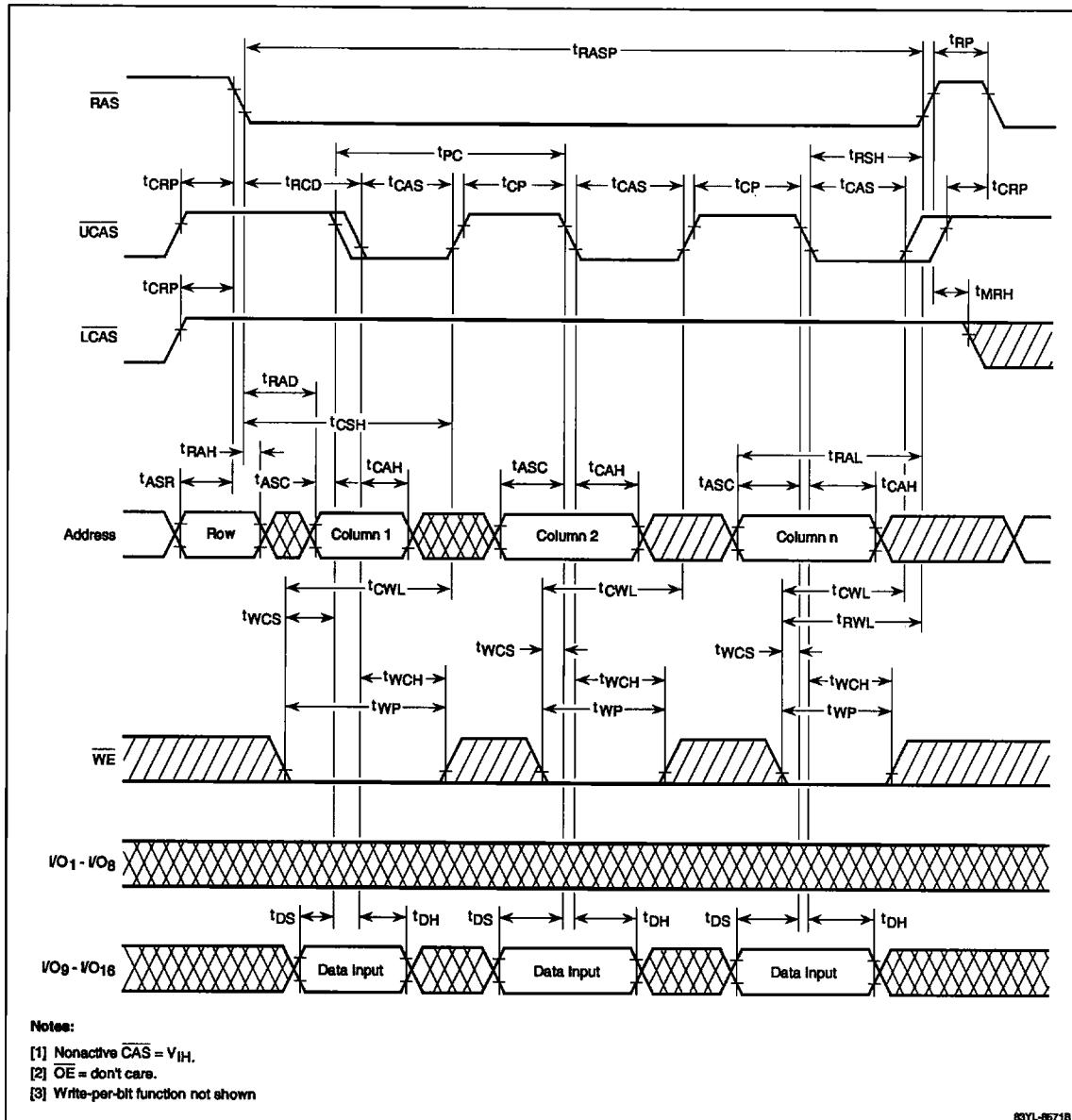
Timing Waveforms (cont)

Word Fast-Page Early-Write Cycle



Timing Waveforms (cont)

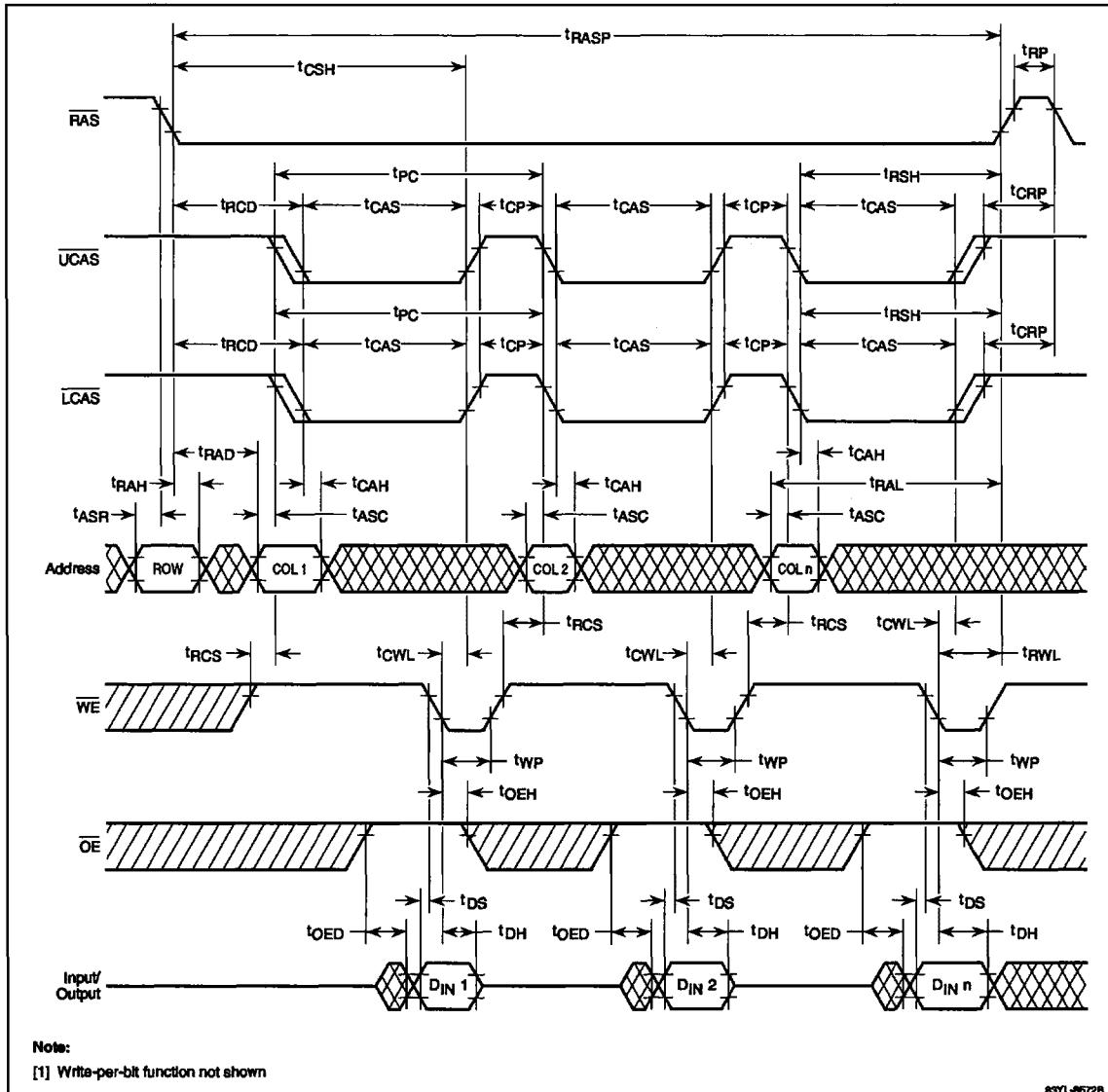
Byte Fast-Page Early-Write Cycle



7d

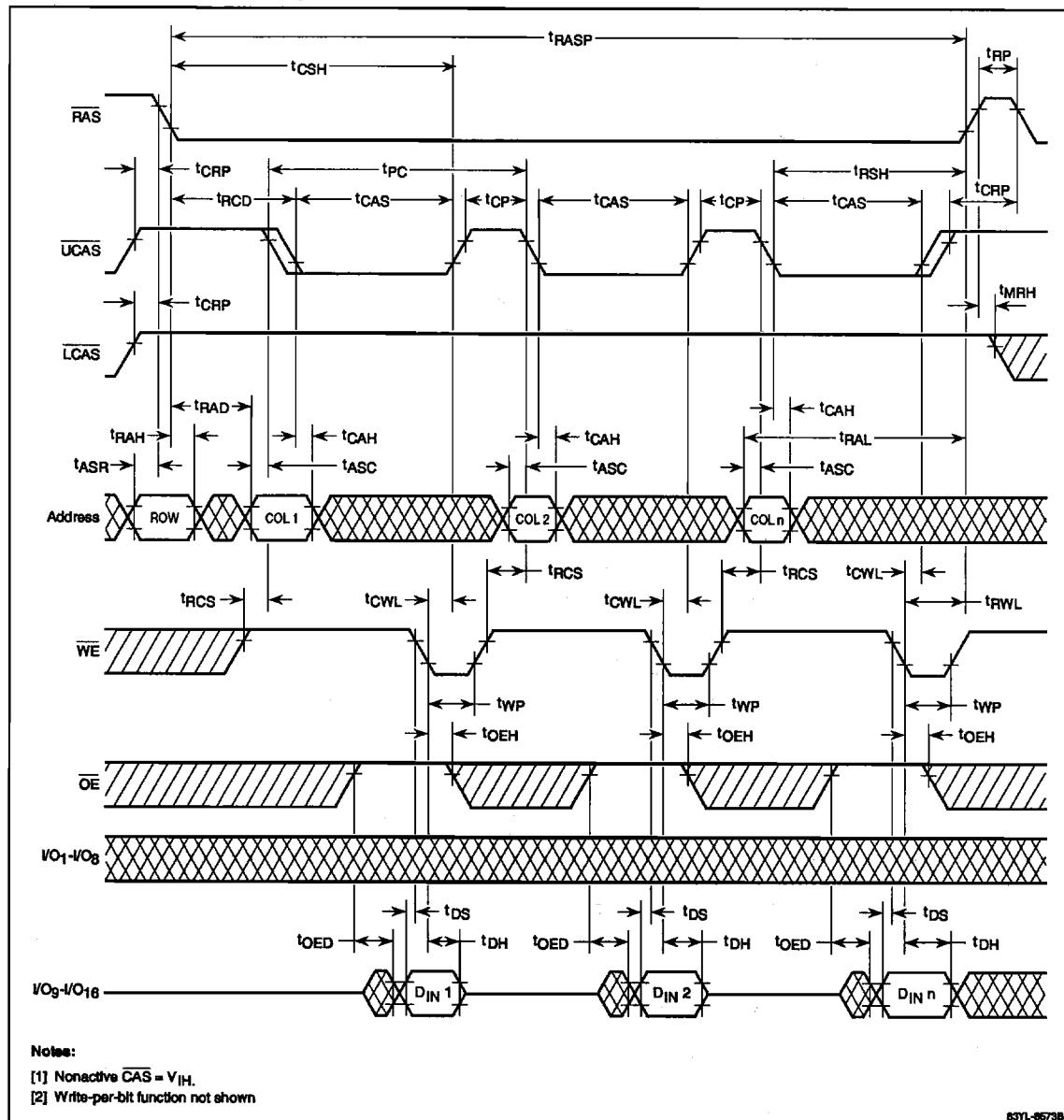
Timing Waveforms (cont)

Word Fast-Page Late-Write Cycle



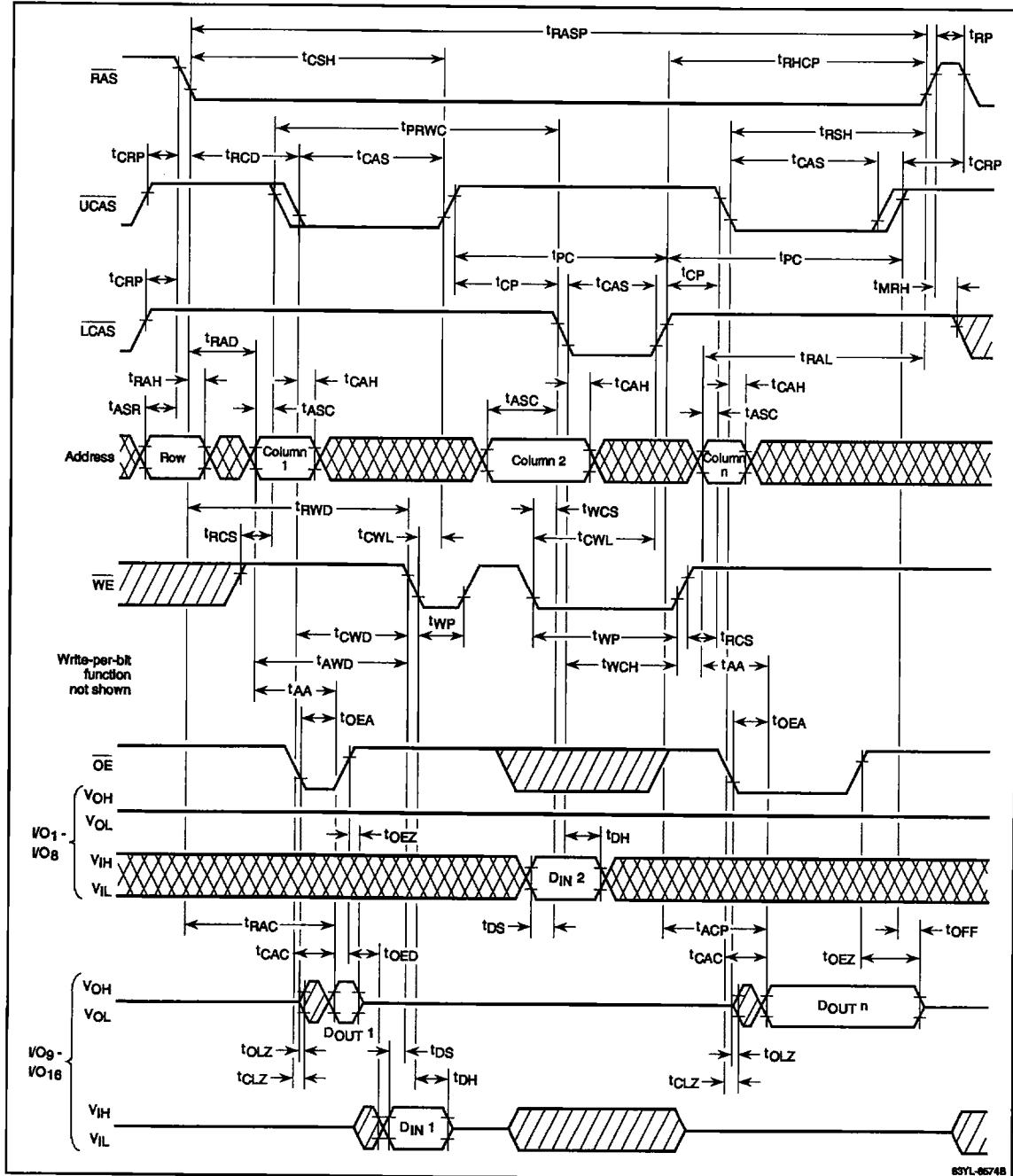
Timing Waveforms (cont)

Byte Fast-Page Late-Write Cycle



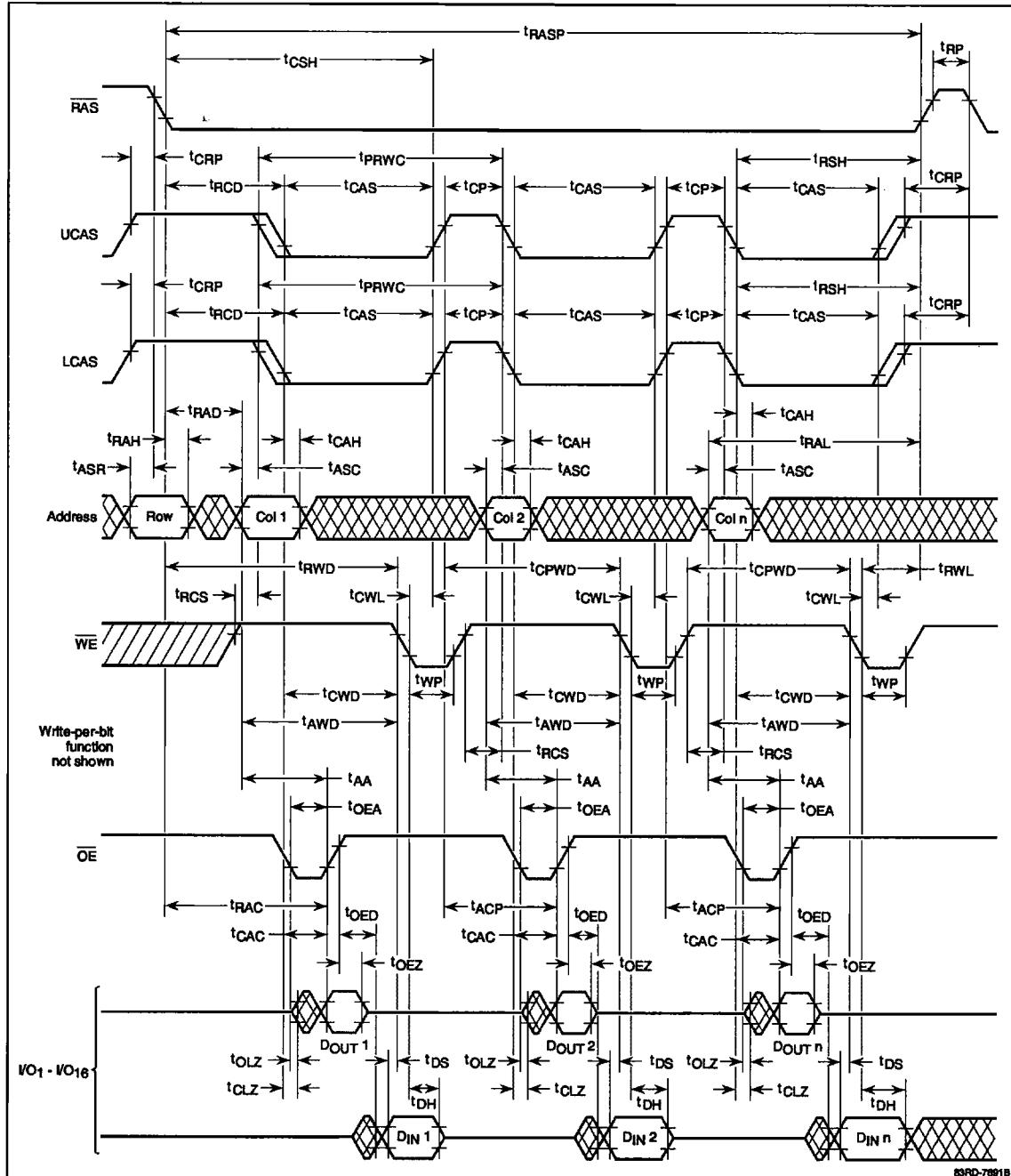
Timing Waveforms (cont)

Byte Fast-Page Read/Write Cycle



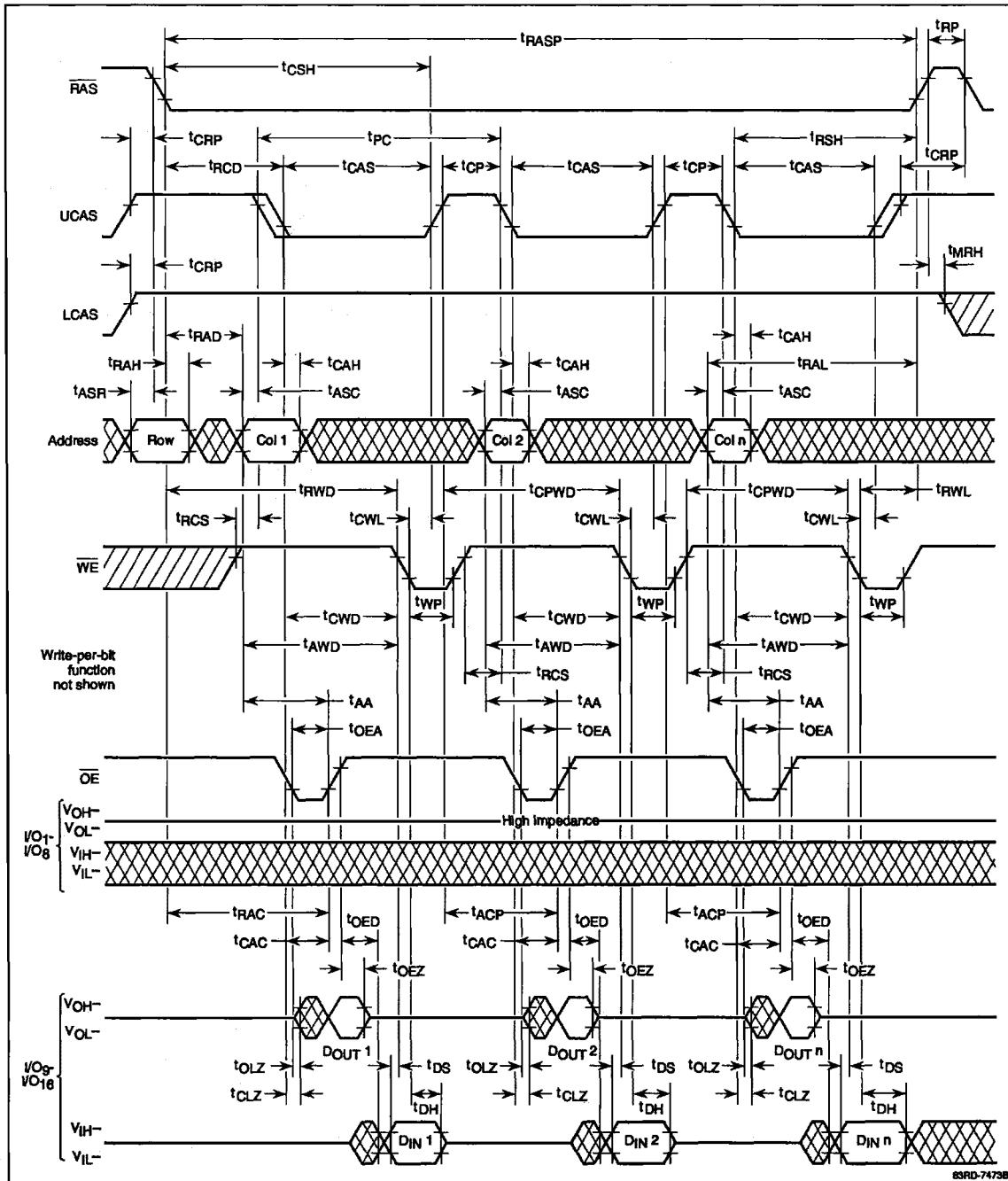
Timing Waveforms (cont)

Word Fast-Page Read-Modify-Write Cycle



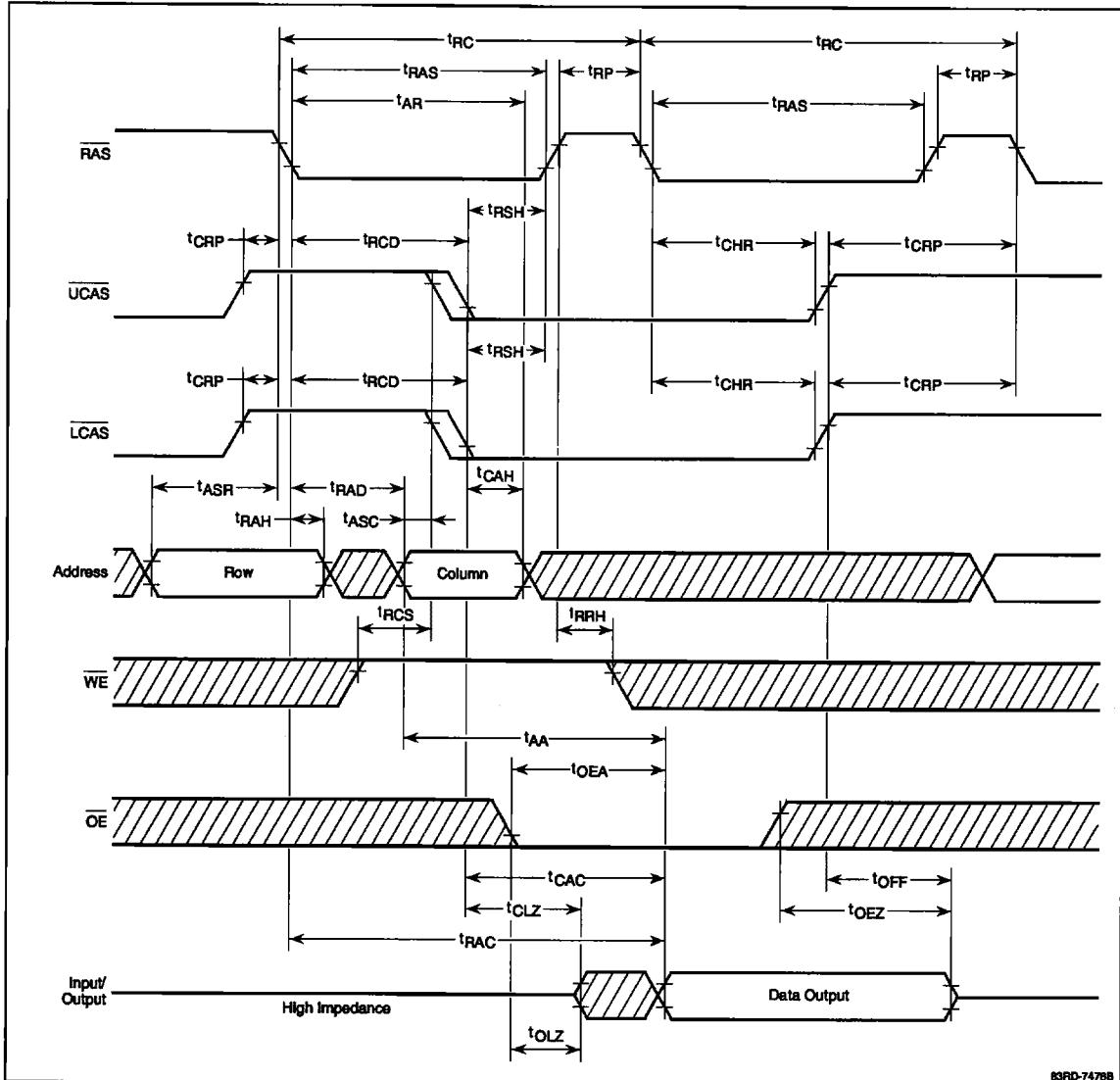
Timing Waveforms (cont)

Byte Fast-Page Read-Modify-Write Cycle



Timing Waveforms (cont)

Hidden Refresh Cycle (Word Read Cycle)

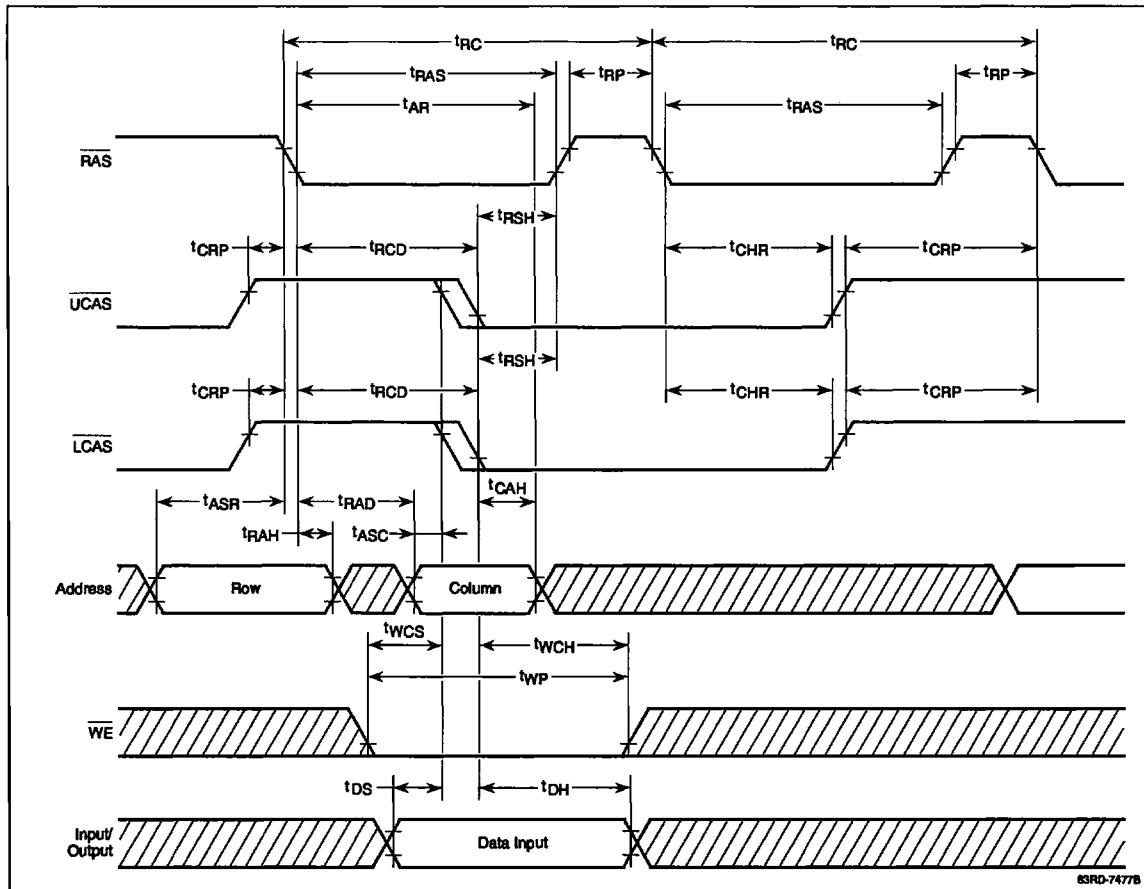


7d

83RD-7478B

Timing Waveforms (cont)

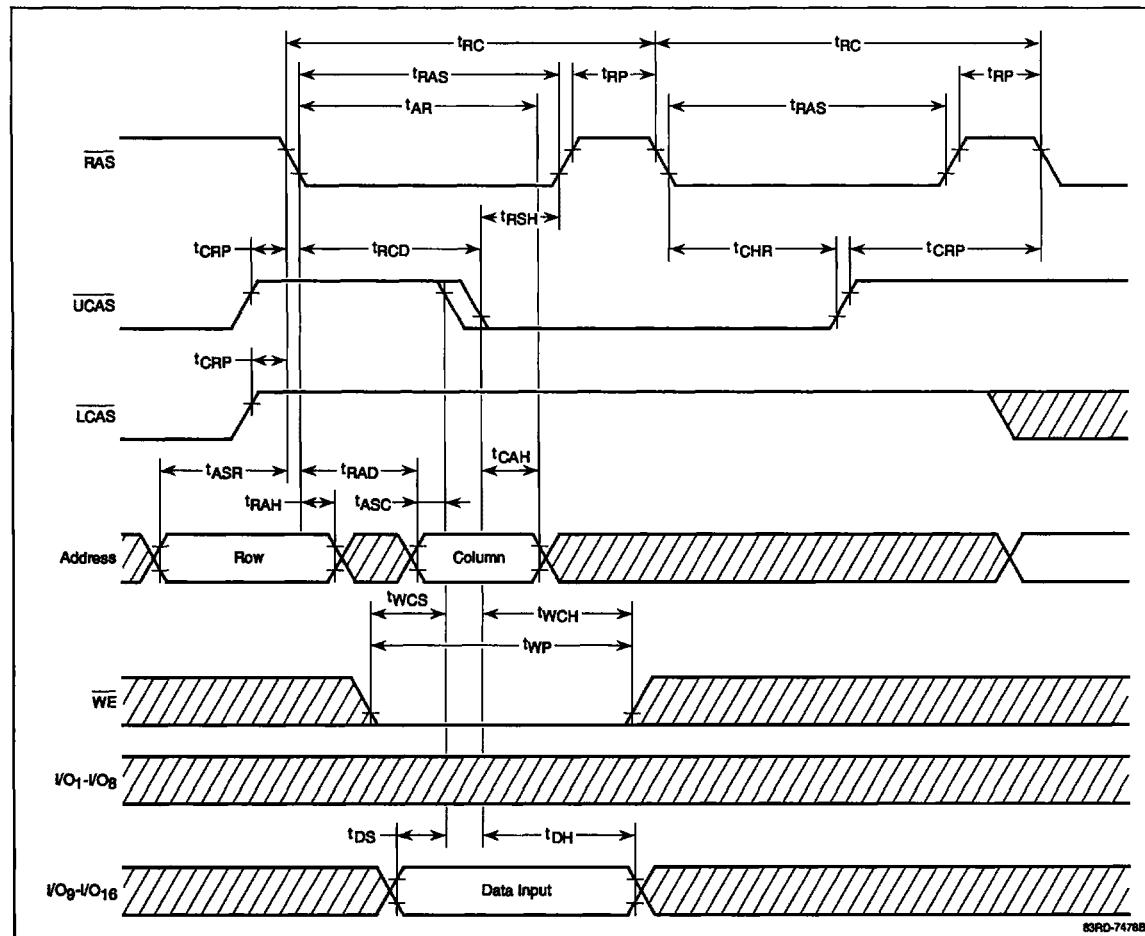
Hidden Refresh Cycle (Word Write Cycle)



63RD-7477B

Timing Waveforms (cont)

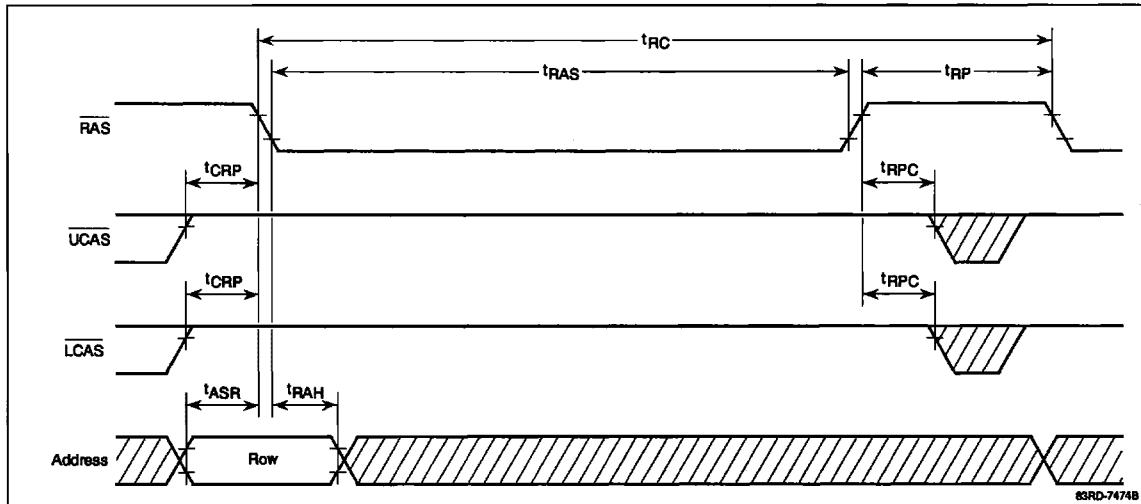
Hidden Refresh Cycle (Byte Write Cycle)



7d

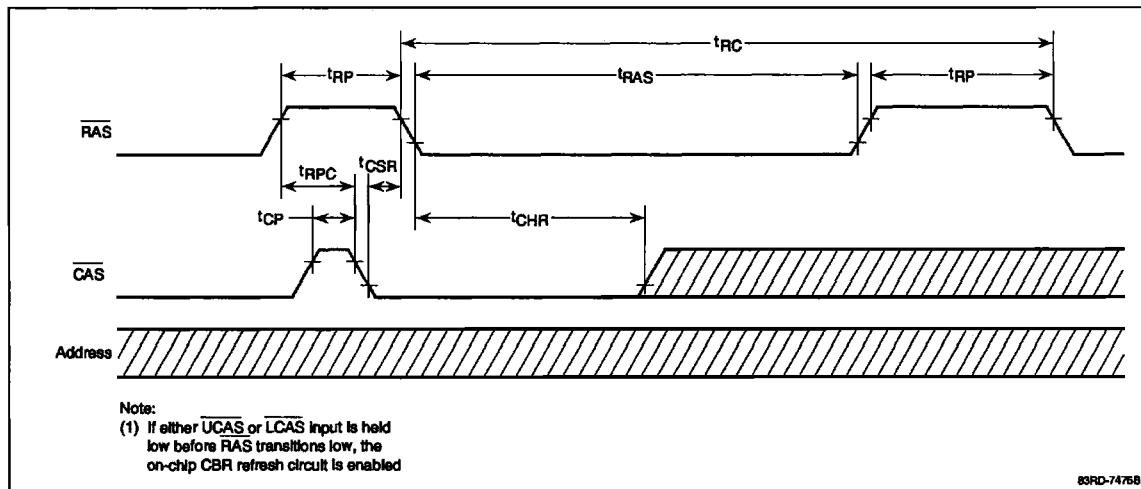
Timing Waveforms (cont)

RAS-Only Refresh Cycle



83RD-7474B

CAS Before RAS Refresh Cycle



Note:

- (1) If either UCAS or LCAS input is held low before RAS transitions low, the on-chip CBR refresh circuit is enabled

83RD-7476B